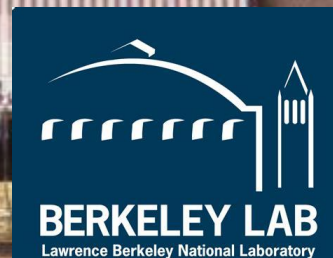


RD53 Status and the Role of Verification in Digital Design

- CPAD 2019 Dec. 8-10, 2019
- Cesar Gonzalez Renteria (LBNL) on behalf of the RD53 Collaboration

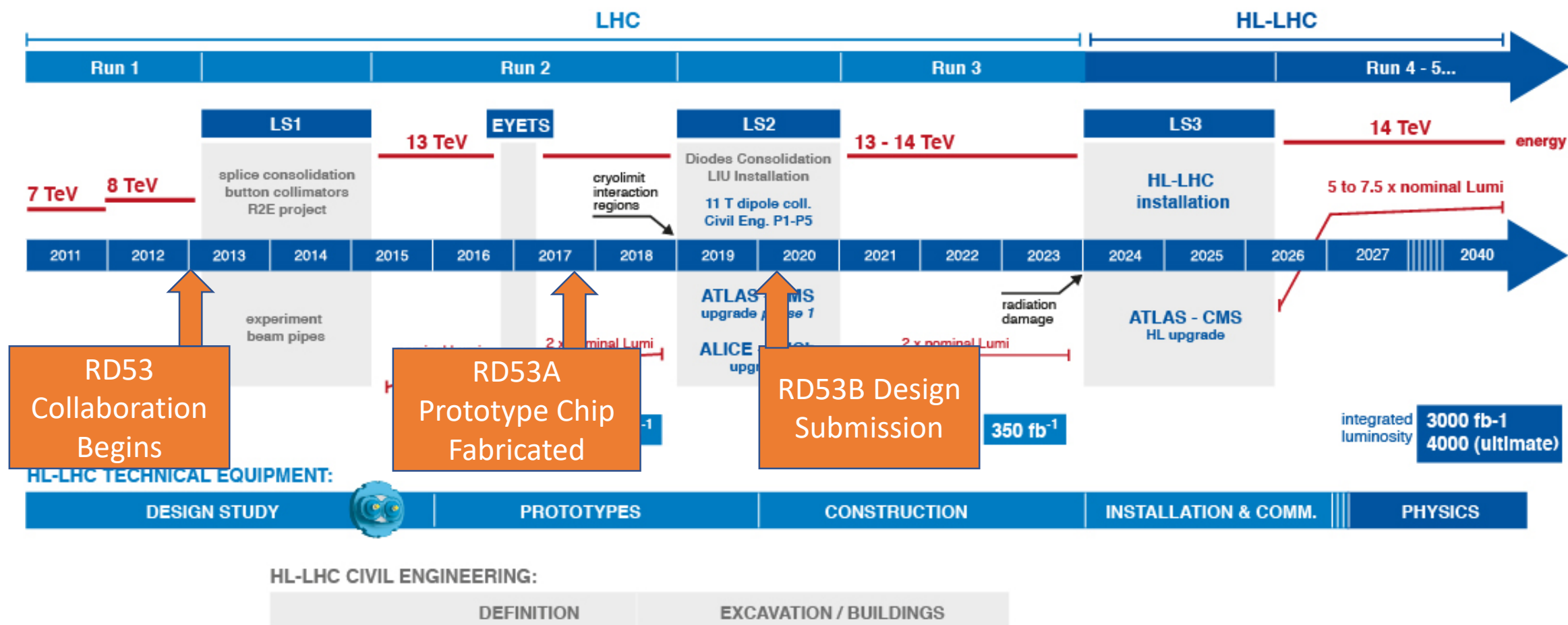


Outline

- Introduction
- RD53 Collaboration
 - What is the mission of the collaboration and what is the final result
- Verification
 - What is verification and how is it used
- Verification of the RD53B Chip
 - Structure of the verification workbench in the case of RD53B



LHC / HL-LHC Plan



RD53 Collaboration

- Focused R&D to develop pixel chips for both ATLAS and CMS upgrades
- Established recognizing that HL-LHC pixel requirements were extremely challenging, yet very similar for both experiment, and a joint effort was the best way to meet them
- At the request of the experiments, last year the mandate of RD53 was extended to design the final production chips for ATLAS and CMS
 - Keep the design team together.
 - Pursue as much as possible a common design to serve the needs of both experiments.
- RD53 has 22 collaborating institutes and many Guests
 - Roughly 20 designers on RD53B Chip (next slide)
 - ~100 conference talks/proceedings/papers to date



RD53 Collaboration

- US Institutes:
 - Lawrence Berkeley National Laboratory
 - University of California, Santa Cruz
 - Fermi National Laboratory
 - University of New Mexico

Collaboration board chair:
Lino Demaria, Torino

Interface to experiments: Co-spokespersons

Jorgen Christiansen, CERN (CMS) , **Maurice Garcia-Sciveres, LBNL (ATLAS)**
 • General organization, Funding, Specifications,

Experiment observers

Duccio Abbaneo, CERN (CMS) ,
Kevin Einsweiler, LBNL (ATLAS)

RD53 design framework for final pixel chips: Flavio Loddo, Bari; Deputy: Tomasz Hemperek, Bonn

Floorplan/integration:
Flavio Loddo, Bari

- Pixel array, Bump pad, EOC, Power distribution, Bias distribution, Analog/digital isolation, Integration, Verification

Analog FEs with biasing:

Luigi Gaioni, Bergamo;

Ennio Monteil, Torino;

Amanda Krieger, LBNL

- Specification/performance, Interface, Analog isolation, simulation model, Abstract, Integration, Verification

Monitoring:

Mohsine Menouni, CPPM;

Gianluca Traversi, Bergamo,

IP designers

- Specification/performance, Interface, Analog isolation, simulation model, Abstract, Integration, Verification

PAD frame: Hans Krueger, Bonn

CDR/PLL: Piotr Rymaszewski, Bonn

High speed drv: Konstantinos

Moustakas, Tianyang Wang, Bonn

Diff. IO: Gianluca Traversi, Bergamo

Digital integration:

Tomasz Hemperek, Bonn; Luca Pacher, Torino

• **Simulation Framework:**

Sara Marconi, CERN;

- Framework, Hit generation/ import MC, Reference model / score board, Monitoring/verification tools, Readout rate estimations, Behavioural pixel chip, SEU injection.

• **Pixel array logic:**

Sara Marconi, CERN

- FE interface, Latency buffer, Core/column bus

• **Digital chip bottom:**

Roberto Beccherle, Pisa; Francesco Crescioli, LPNHE;

- Configuration, Control interface, Readout data format/protocol, Compression

• **Verification:**

Sara Marconi, CERN; Attiq Rehman, Bergen,

Joel De Witt, Santa Cruz

Cesar Gonzales Renteria, LBNL

Peilian Liu, LBNL

SEU: Pedro Leita, CERN; Rafael Girona, Sevilla

SET: Fernando Munoz Chavero, Sevilla

LPGBT: Pedro Leita, CERN

Mixed signal: Luca Pacher, Torino;

Aikaterini Papadopoulou, LBNL

- Functional, SEU, Interfaces, specifications

• **Library cells:**

DICE: Denis Fougeron, Mohsine Menouni, CPPM

Timing characterization : Sandeep Miryala, FNL

Serial Power:

SLDO: Michael Karagounis,
Andreas Stiller, Dortmund.
Bandgap: Gianluca Traversi,

Verification: Alvaro Pradas, ITAINNOVA;
Stella Orfanelli, CERN; Dominik Koukola, CERN

- Shunt-LDO integration, On-chip power distribution, Optimization for serial powering, System level power aspects, Power Verification

Design for testability:

Giuseppe De Robertis, Bari

- Scan path, BIST, production test patterns, Fault simulation, bump bonding testing

IPs: Support and possible updates

Current DAC: Bari

Voltage DAC: Prague

ADC, mux, temp: CPPM

Power on reset: Seville

Ring oscillator: LAL

Analog buffer: RAL

Support and services:

Tools, design kit: Wojciech Bialas, CERN

Repositories: Flavio Loddo, Bari; Luca

Pacher, Torino; Tomasz Hemperek, Bonn

Radiation model: Mohsine Menouni, CPPM;

CERN

Testing: Timon Heim, LBNL

YARR system: Timon Heim, LBNL

BDAQ53 system: Marco Vogt, Michael Daas, Yannik Dieter, Hans Krueger, Tomasz Hemperek,
Mark Standtke Bonn

Radiation test: Luis Miguel Jara Casas, CERN, Mohsine Menouni, CPPM.

Plus many ATLAS/CMS groups not formally part of RD53

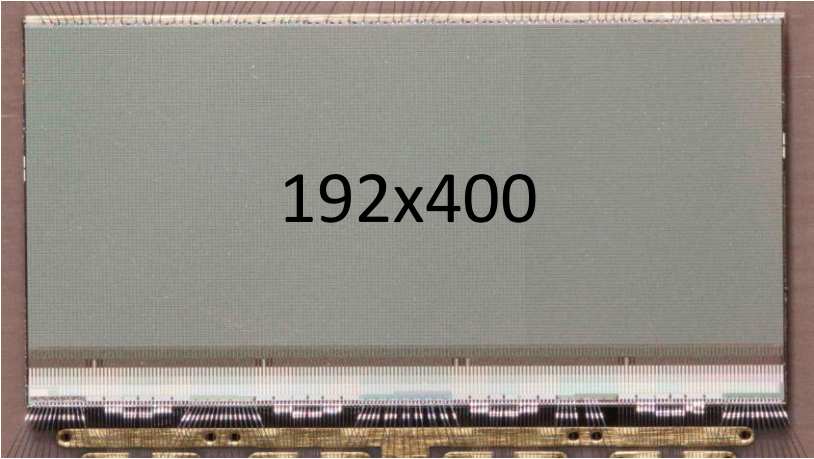
Pixel sensor and bump-bonding:

Fabian Huegging, Bonn (ATLAS),

Georg Steinbrueck, Hamburg (CMS)

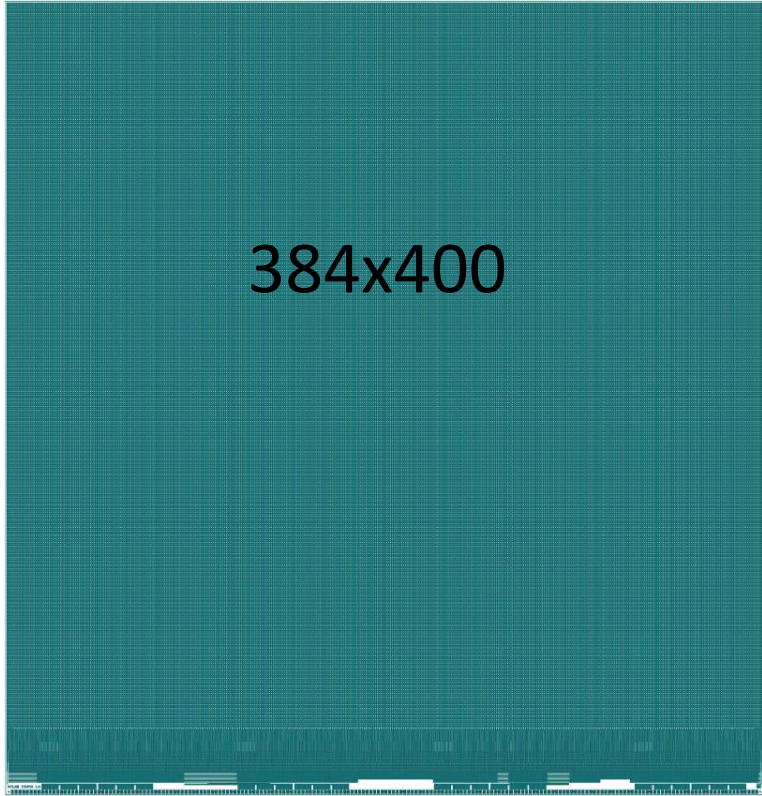
Names in bold: Member of RD53 management board

Picture of RD53A, B-ATLAS, B-CMS

A photograph of the RD53A chip, which is a rectangular silicon detector with a grey surface and a gold-colored base with pins.

192x400

RD53A Chip

A photograph of the RD53B-ATLAS chip, which is a square silicon detector with a teal surface and a gold-colored base with pins.

384x400

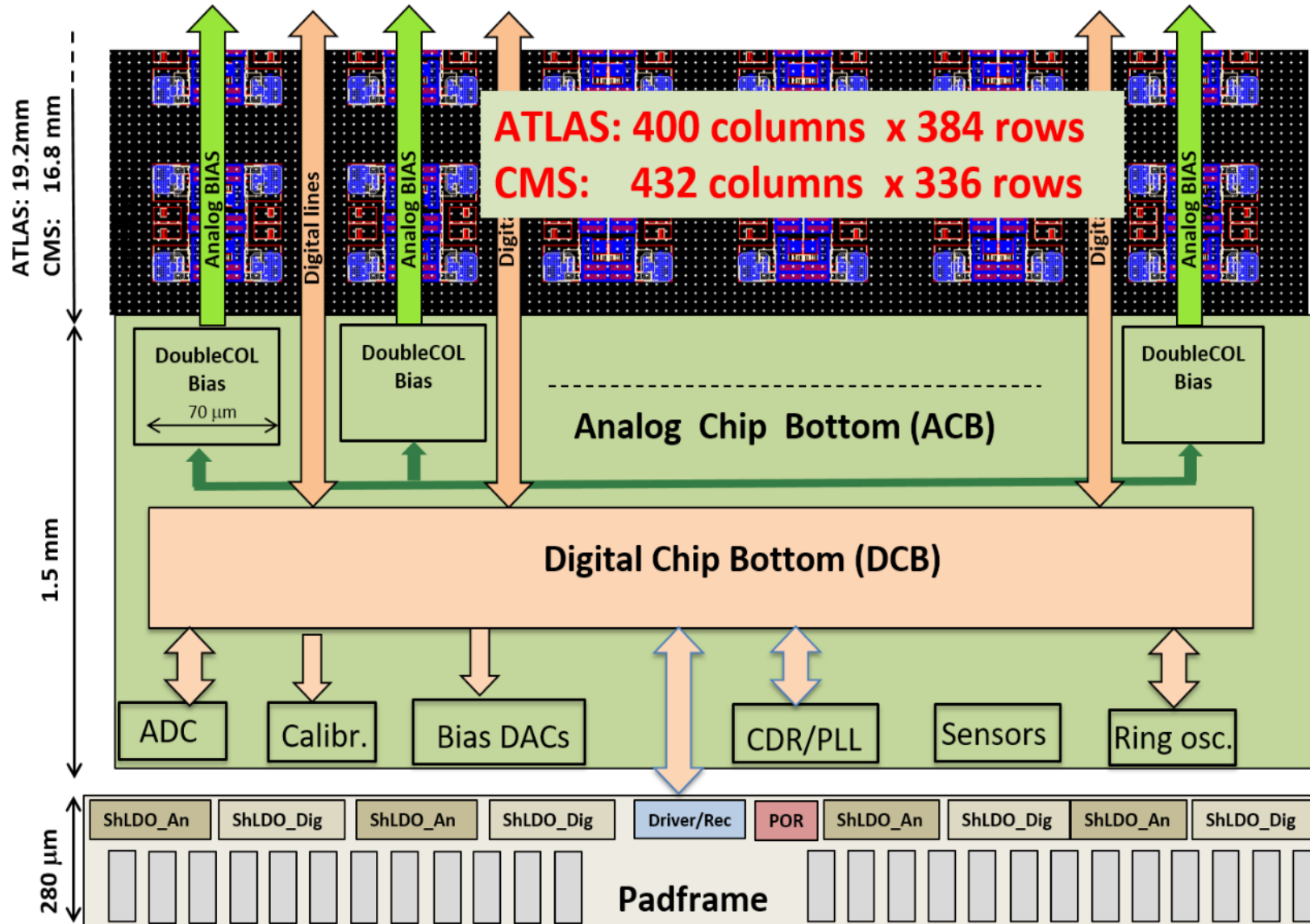
RD53B-ATLAS Chip

A photograph of the RD53B-CMS chip, which is a square silicon detector with a green surface and a gold-colored base with pins.

336x432

RD53B-CMS Chip

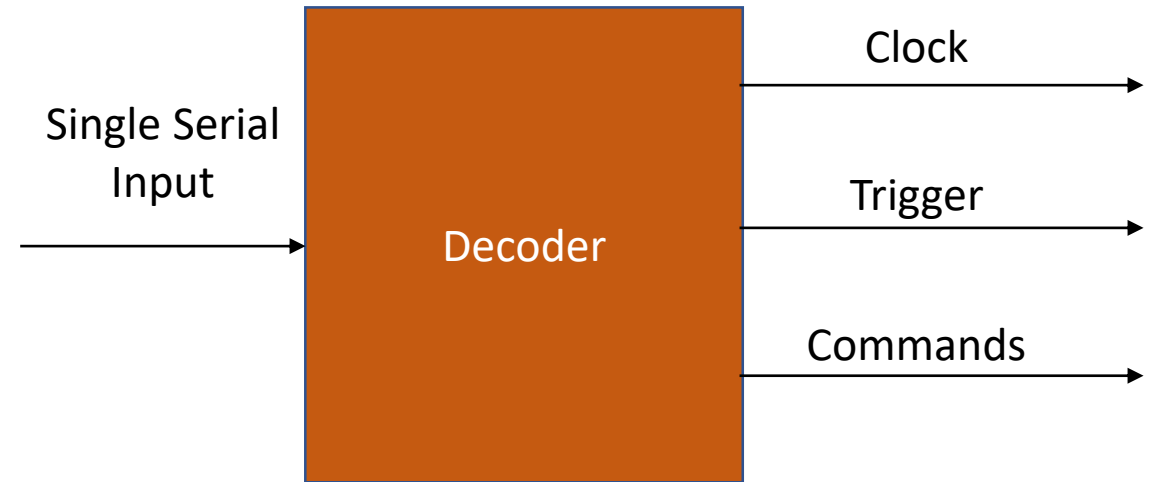
RD53B Chip Design



- Read-Out ASIC for both experiments which communicates with Pixel Matrix and DAQ system
- Analog portion of chip done the standard way.
- Digital part is extremely complicated and makes up most of the design.

Example of Digital Complexity: I/O

- Three main signals necessary for chip operation:
 - Bunch Crossing **Clock**
 - **Trigger** (Synchronous)
 - **Commands** (Configuration)
- In order to eliminate massive amounts of service lines, designed a scheme that sends all three in one serial stream.



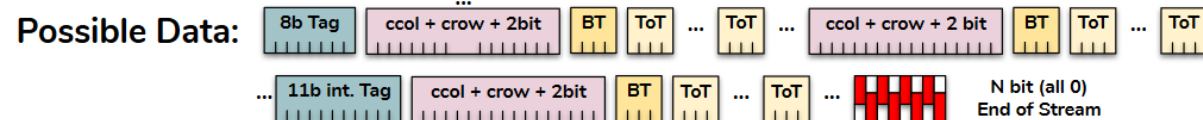
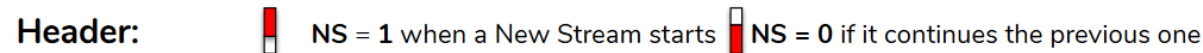
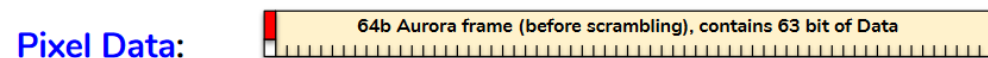
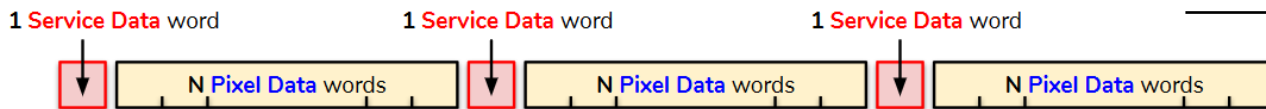
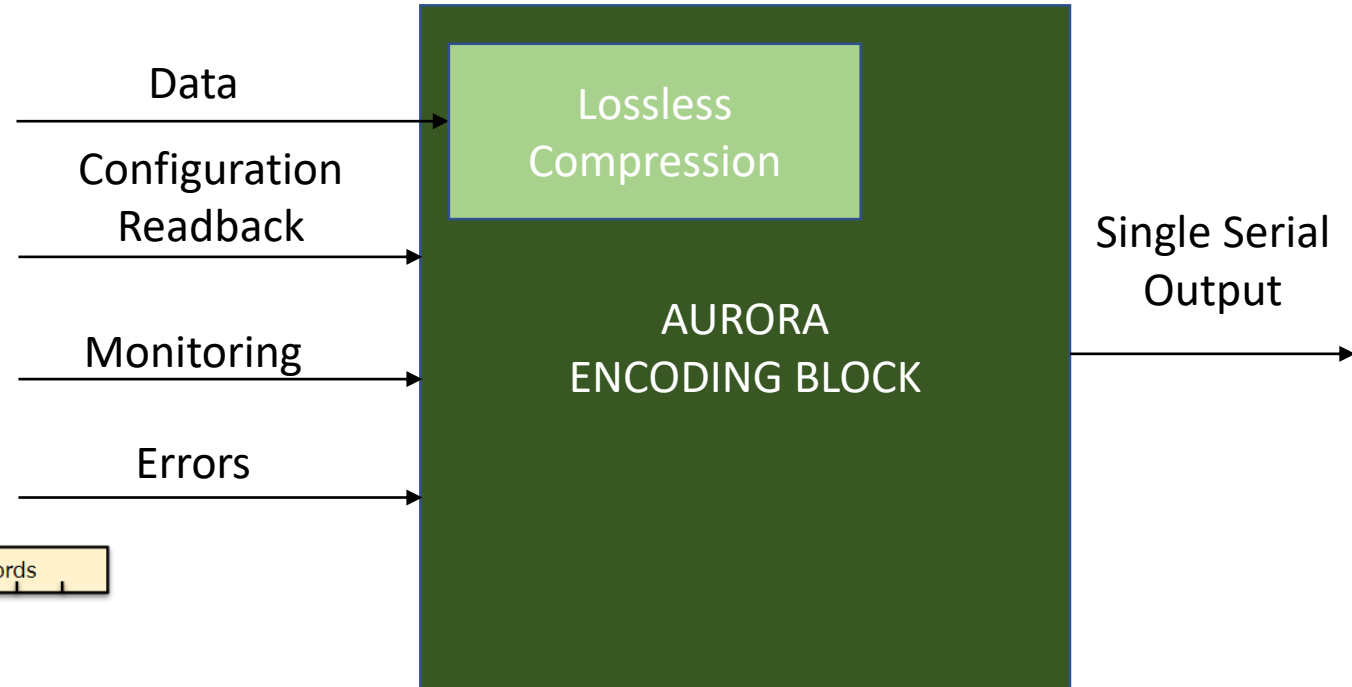
Structure of the Serial Stream

- Designed encoding scheme to make sure signals are synchronous to BC Clock, DC Balanced (AC coupling compatible due to serial power)
- Trigger/Commands sent in 16 bit frames made of 2 8-bit symbols
- Each Trigger/Command has a encoded symbol which defines it (52 total encoded symbols)
- Will comment later on how chip decodes this bit stream

Command	Encoding		(T)ag, (A)ddress or (D)ata 5-bit content						
Sync	1000_0001	0111_1110							
PLLlock (noop)	1010_1010	1010_1010							
Trigger	tttt_tttt	Tag[0..53]							
Read_trigger	0110_1001	ID<4:0>	00,T<7:5>	T<4:0>					
Clear	0101_1010	ID<4:0>							
Global Pulse	0101_1100	ID<4:0>							
Cal	0110_0011	ID<4:0>	D<19:15>	D<14:10>	D<9:5>	D<4:0>			
WrReg(0)	0110_0110	ID<4:0>	0,A<8:5>	A<4:0>	D<15:11>	D<10:6>	D<5:1>	D<0>,0000	
WrReg(1)	0110_0110	ID<4:0>	1,A<8:5>	A<4:0>	N×(D<9:5>	D<4:0>)			
RdReg	0110_0101	ID<4:0>	0,A<8:5>	A<4:0>					

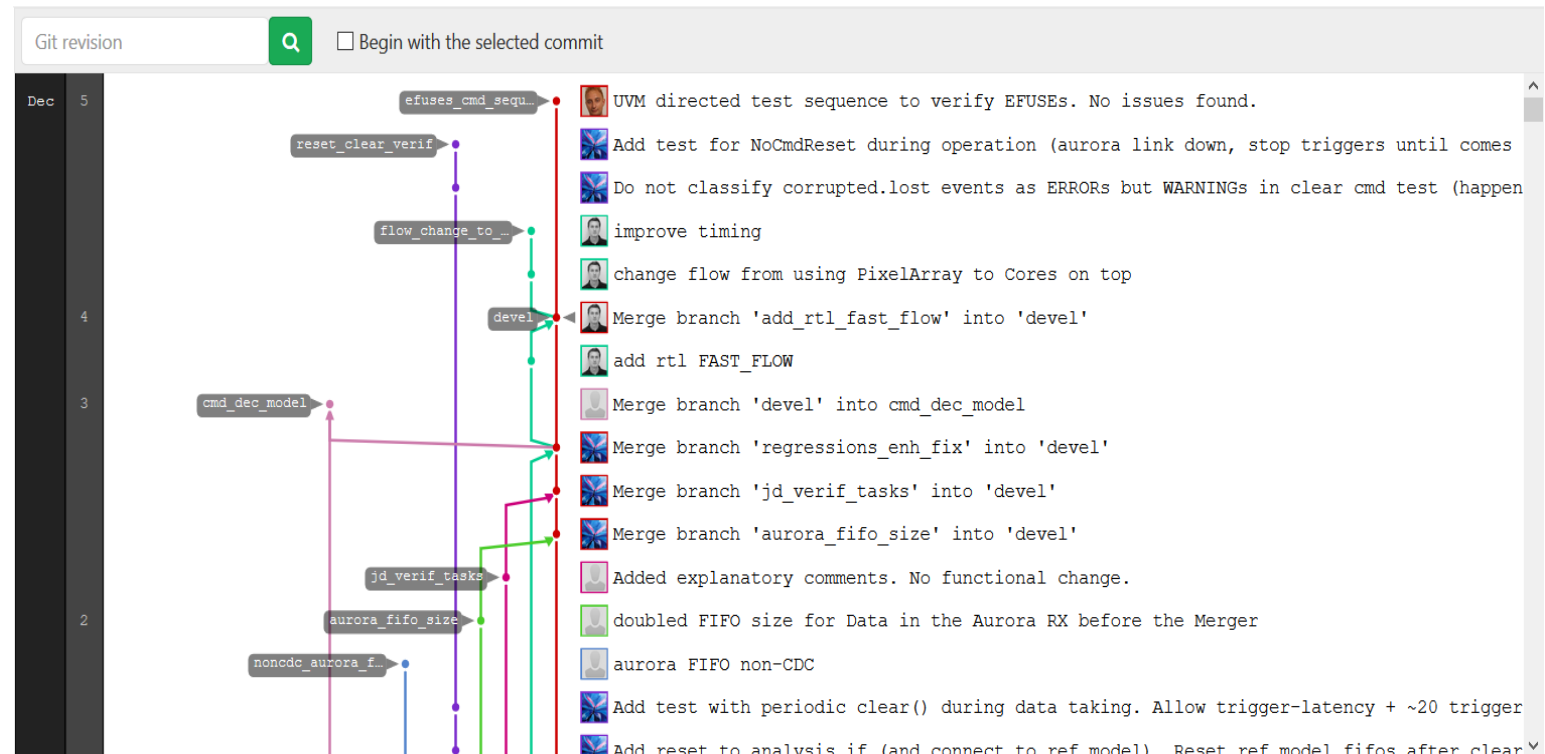
Output: Aurora Encoding

- Output to DAQ is asynchronous
- Encode multiple signals using Aurora 64b/66b encoding.
- Industry standard encoding protocol similar to ethernet protocol
- Makeup of Aurora Frame designed to be efficient



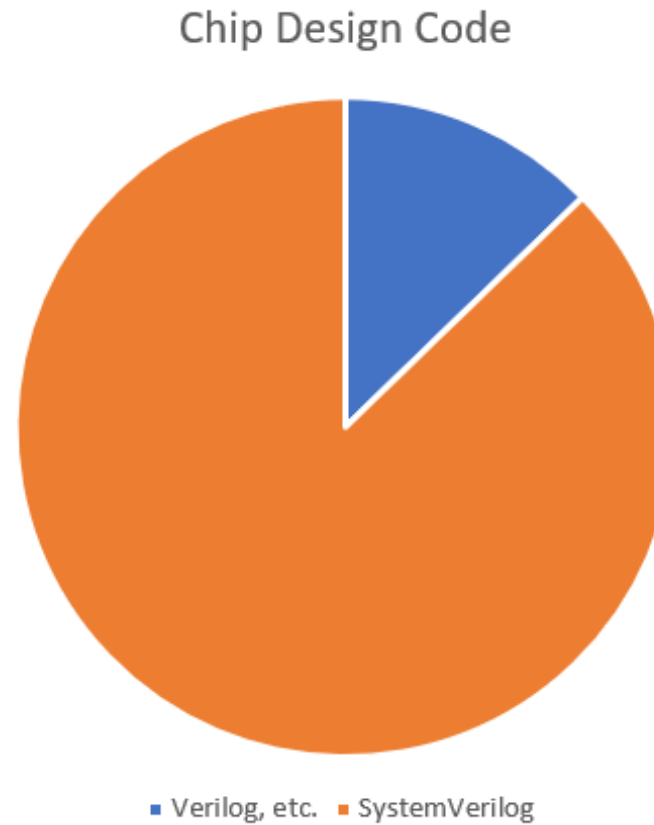
Digital Chip Design is a Software Project

- **System Verilog** is a hardware verification and description language similar to C++ but with built in abstractions for hardware objects, ability to **manipulate time**, and dynamically allocate memory.
- Built from **Verilog** which was similar to C. Verilog is missing C++-style objects, assertions and coverage groups.
- **UVM (Universal Verification Methodology)** is a pre-built library written in SV with a full verification testbench structure in place inherited by UVM classes.
- Through Verilog, SV & UVM you can:
 - Write up the logic and parts that make up the chip (DUT).
 - Write up the testbench to stimulate the DUT and analyze the results.



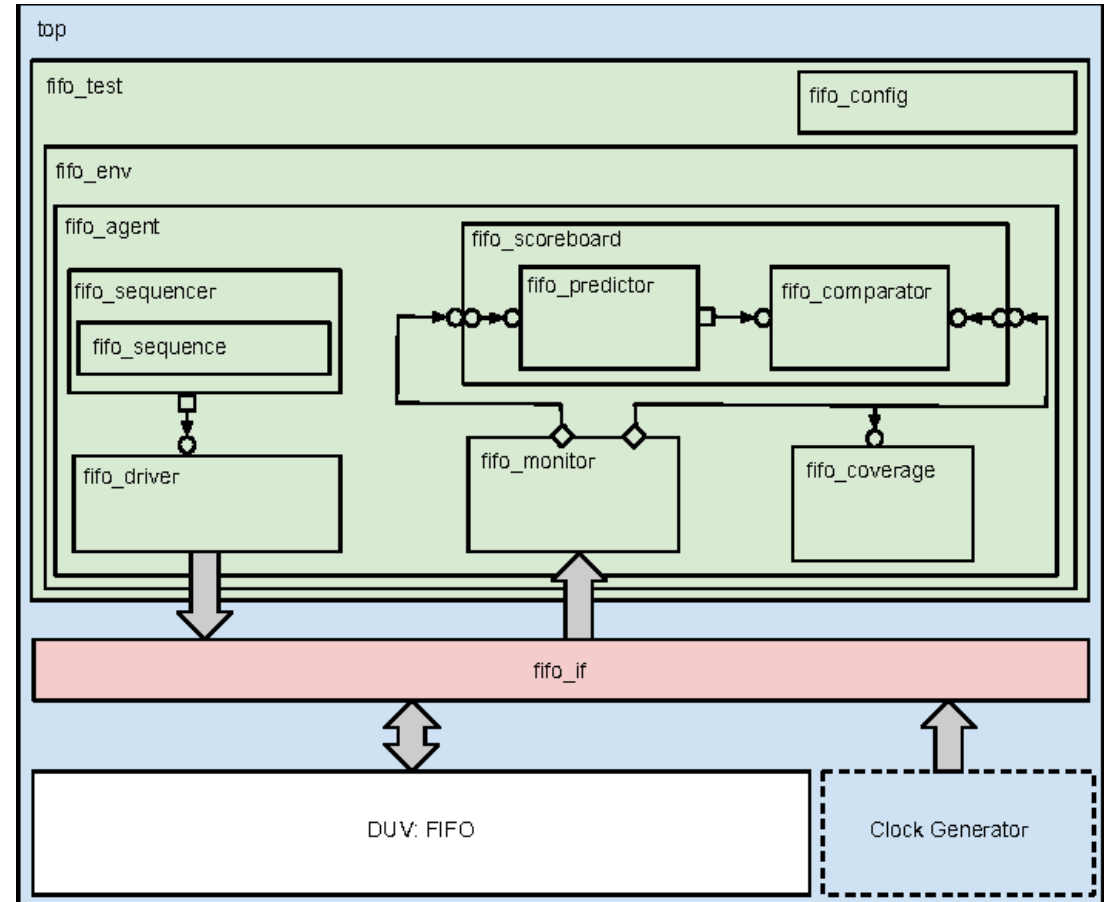
**** The Chip Design for RD53B is all software!!****

- **Digital Code in the Chip:**
- There are 123 different SystemVerilog files and each file corresponds (mostly) to one module.
- 87% of files written in SystemVerilog
- There are ~20k lines of code.
- **Verification Code:**
- There are 392 different SystemVerilog files
- 90% of files written in SystemVerilog
- There are ~120k lines of code.



Example: Verifying a FIFO Design

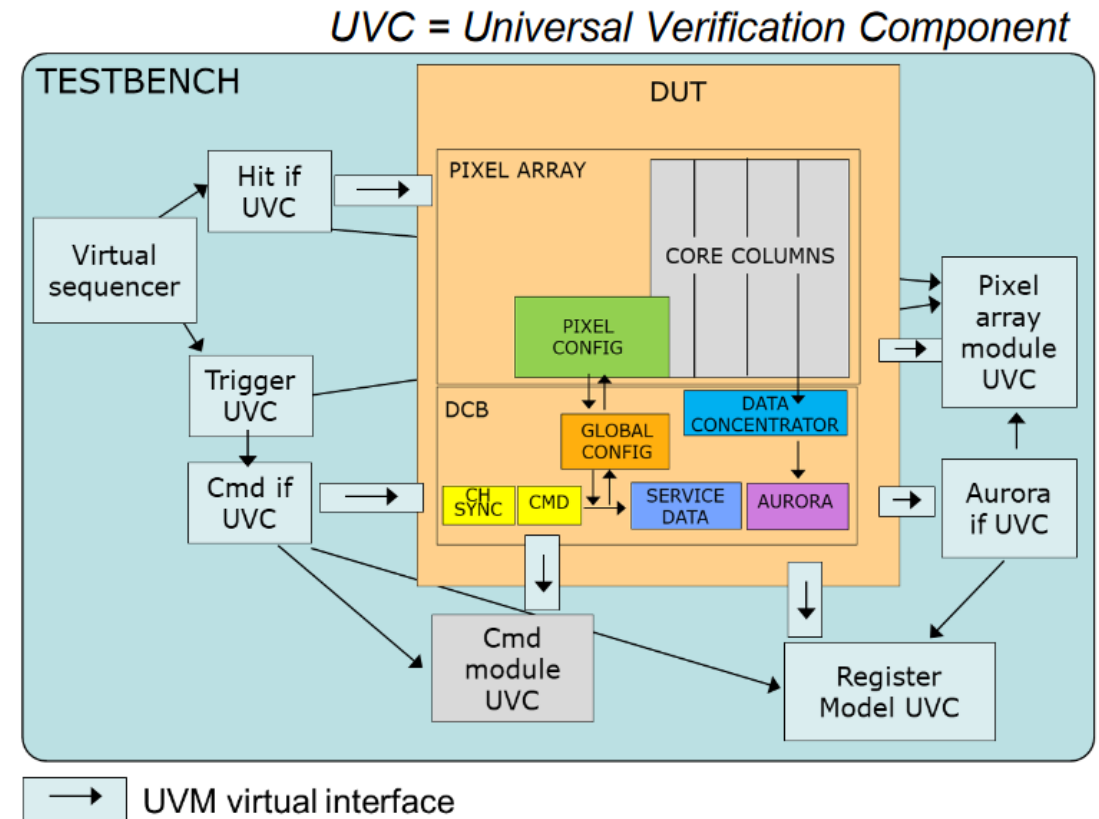
- The top of the workbench is the **test**.
- Sample test can be as follows:
 - Write to FIFO (**Driver**)
 - Check state and size of FIFO before and after write (**Monitor**)
 - Read from FIFO (**Driver**)
 - Check state and size of FIFO before and after read (**Monitor**)
 - Verify it matches expectation (**Scoreboard**)
 - I.E. First In – First Out



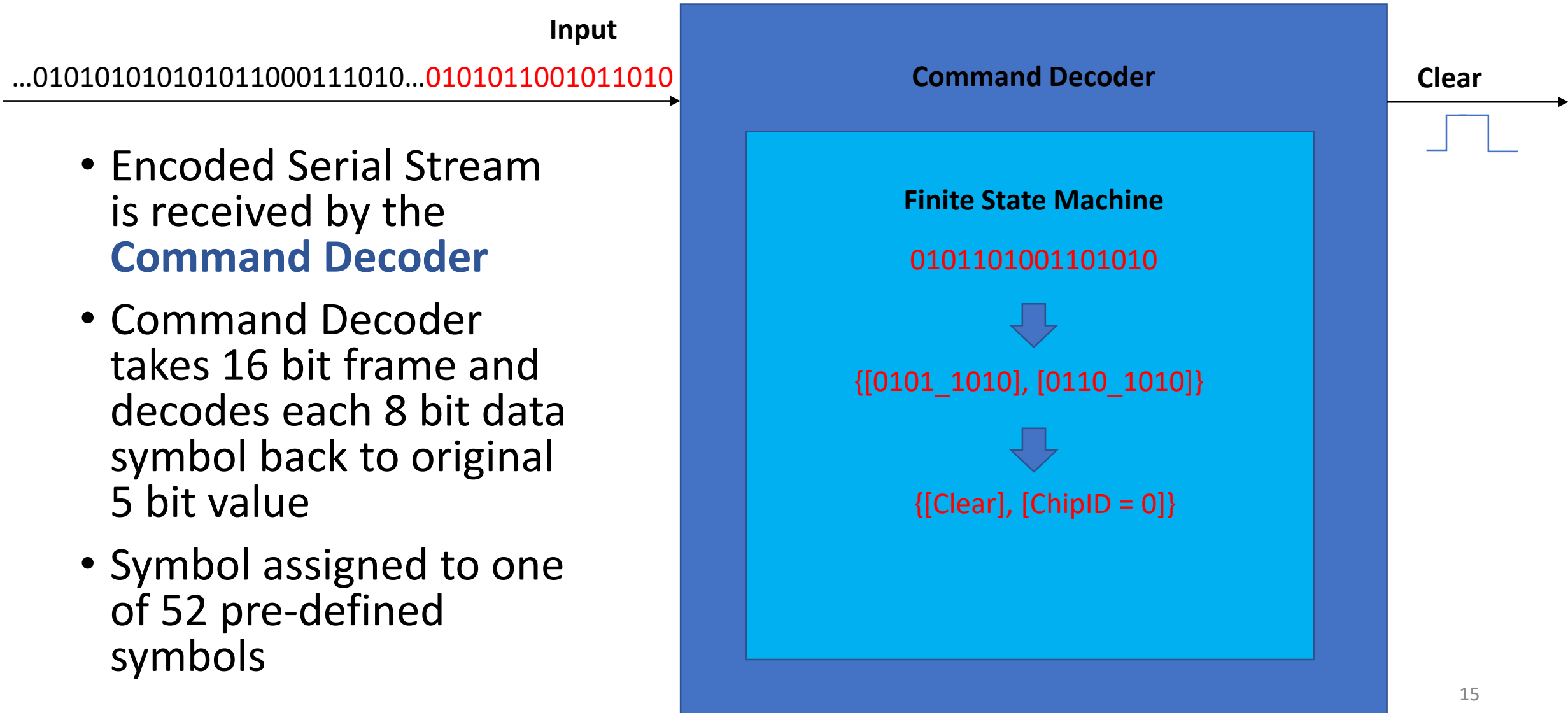
[3]

RD53B Chip UVM Testbench

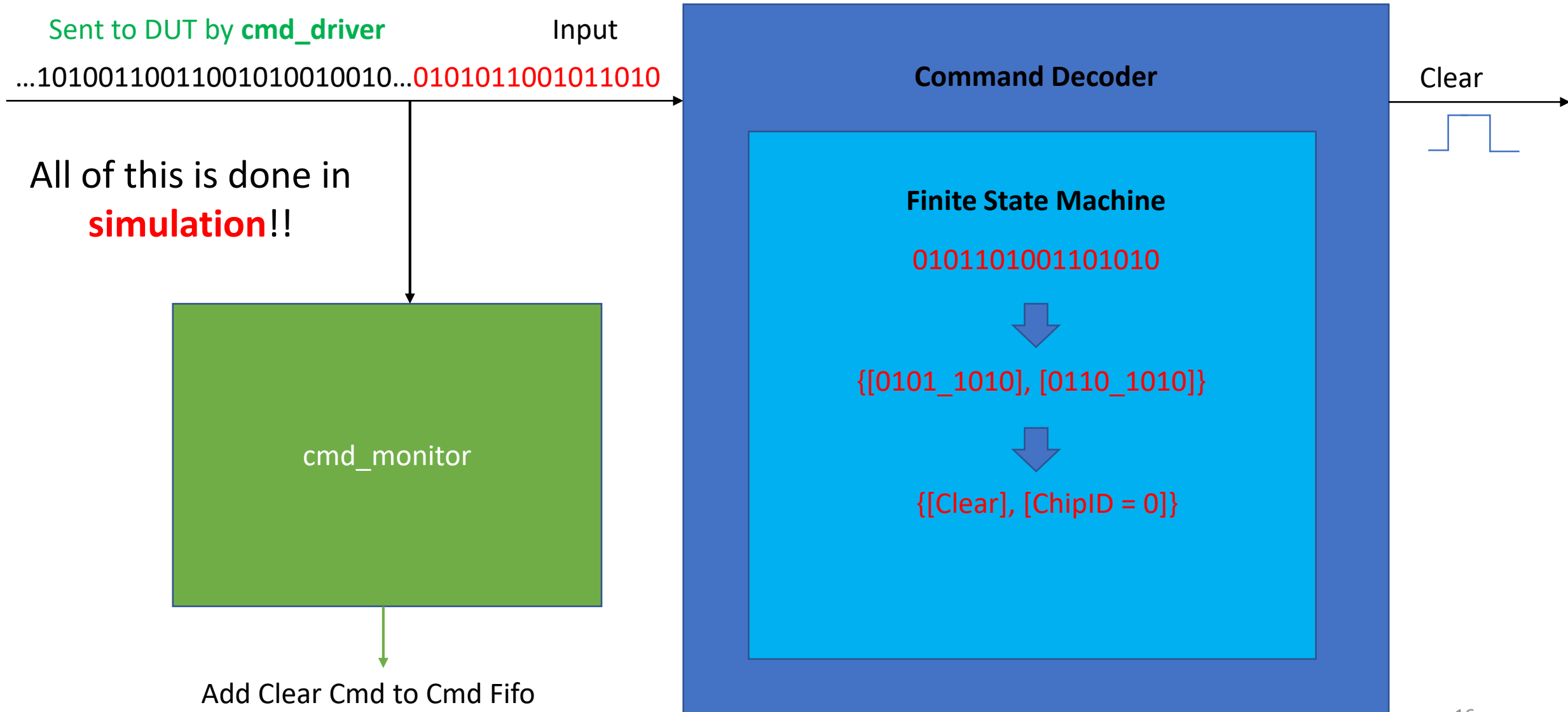
- **Top Test** instantiates multiple Universal Verification Components (UVCs).
- Each UVC is created to test certain blocks of the chip design.
- Each UVC contains its own environment, agent, scoreboard, etc.
- Will show an example of verifying the “CMD” block of the chip



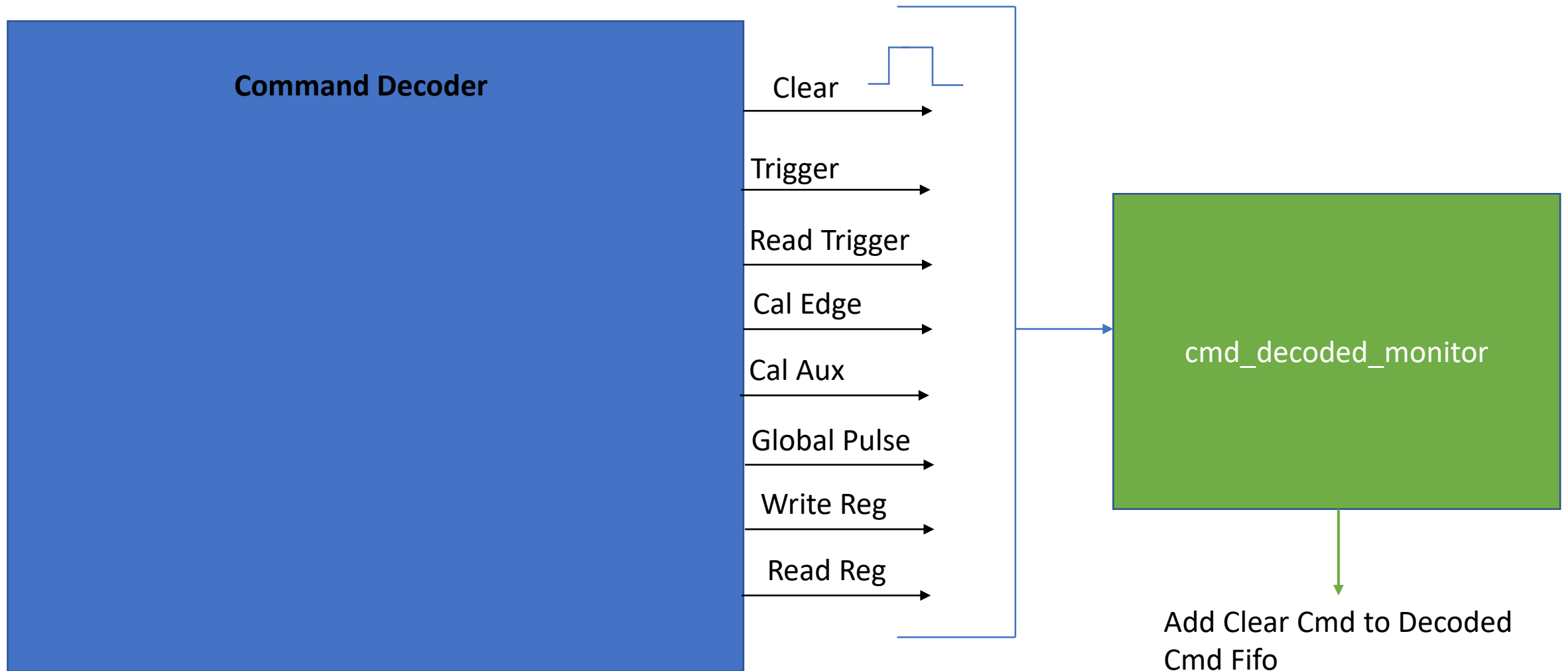
An Example: Verifying the Command Decoder



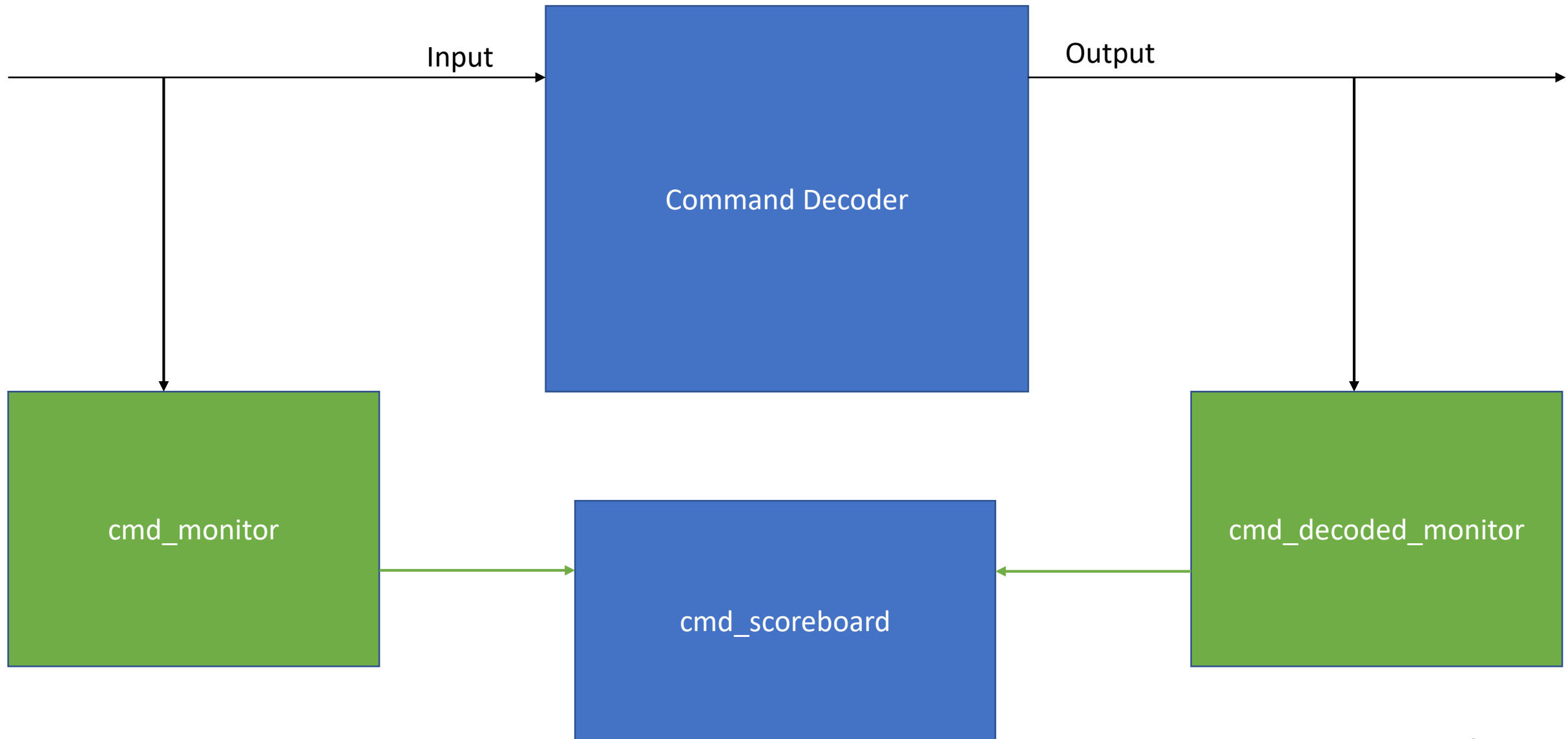
Introducing Verification Structure: UVM Monitor and Driver



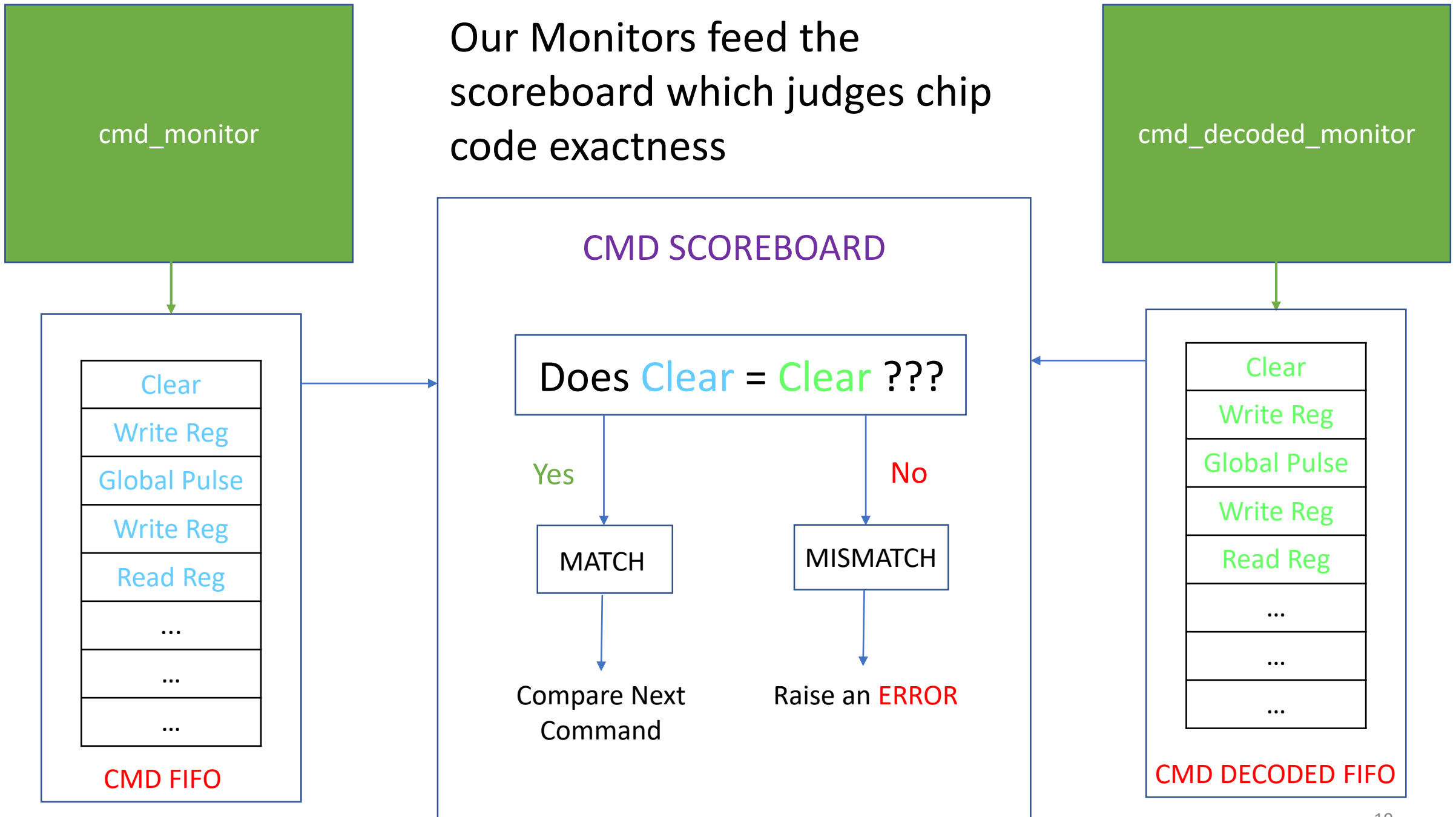
Introducing the Second UVM Monitor



Testing Correct Behavior: UVM Scoreboard



Our Monitors feed the scoreboard which judges chip code exactness



Create a **Test**: Do we see a match?

- 2000 Randomly generated commands sent + extra commands to set up chip
- The data sent with each command is also randomly generated (within allowable values)
- Command Checker finds a match between Decoded and Encoded monitors for every command sent.

```
UVM_INFO
/home/cesar_gr/RD53B/work/sim/../../../../cds/./sim/verification_environment/cmd/sv/cmd_checker.sv(102)
@ 38746145000: uvm_test_top.m_env.m_cmd_analysis_env.m_cmd_checker [CMD_CHECKER_MATCH] WRITE
REGISTER      Chip #31,      no auto-increment, address EnCoreColumnCalibration_1,      data e1 encoded cmd
matches decoded cmd WRITE REGISTER      Chip #31,      no auto-increment, address
EnCoreColumnCalibration_1,      data e1

UVM_INFO
/home/cesar_gr/RD53B/work/sim/../../../../cds/./sim/verification_environment/cmd/sv/cmd_checker.sv(102)
@ 38896289000: uvm_test_top.m_env.m_cmd_analysis_env.m_cmd_checker [CMD_CHECKER_MATCH]
TRIGGER Positions of trigger during frame: 0001; trigger tag: 25 encoded cmd matches decoded cmd
TRIGGER Positions of trigger during frame: 0001; trigger tag: 25

UVM_INFO
/home/cesar_gr/RD53B/work/sim/../../../../cds/./sim/verification_environment/cmd/sv/cmd_checker.sv(102)
@ 39246625000: uvm_test_top.m_env.m_cmd_analysis_env.m_cmd_checker [CMD_CHECKER_MATCH] WRITE
REGISTER      Chip #31,      no auto-increment, address DAC_PREAMP_T_DIFF,      data 15 encoded cmd matches
decoded cmd WRITE REGISTER      Chip #31,      no auto-increment, address DAC_PREAMP_T_DIFF,      data 15

UVM_INFO
/home/cesar_gr/RD53B/work/sim/../../../../cds/./sim/verification_environment/cmd/sv/cmd_checker.sv(102)
@ 39446817000: uvm_test_top.m_env.m_cmd_analysis_env.m_cmd_checker [CMD_CHECKER_MATCH] READ
REGISTER      Chip #31,      address RingOscRoute encoded cmd matches decoded cmd READ REGISTER      Chip #31,
address RingOscRoute

UVM_INFO
/home/cesar_gr/RD53B/work/sim/../../../../cds/./sim/verification_environment/cmd/sv/cmd_monitor.sv(282)
@ 39596961000: uvm_test_top.m_env.m_cmd_env.m_cmd_master_agent.m_cmd_monitor [COMMAND_MONITORING]
TRIGGER Positions of trigger during frame: 0001; trigger tag: 49

UVM_INFO
/home/cesar_gr/RD53B/work/sim/../../../../cds/./sim/verification_environment/cmd/sv/cmd_checker.sv(102)
@ 39647009000: uvm_test_top.m_env.m_cmd_analysis_env.m_cmd_checker [CMD_CHECKER_MATCH] READ
REGISTER      Chip #31,      address DAC_PREAMP_TR_LIN encoded cmd matches decoded cmd READ REGISTER      Chip
#31,      address DAC_PREAMP_TR_LIN

UVM_INFO
/home/cesar_gr/RD53B/work/sim/../../../../cds/./sim/verification_environment/cmd/sv/cmd_checker.sv(102)
@ 39797153000: uvm_test_top.m_env.m_cmd_analysis_env.m_cmd_checker [CMD_CHECKER_MATCH]
TRIGGER Positions of trigger during frame: 0001; trigger tag: 49 encoded cmd matches decoded cmd
TRIGGER Positions of trigger during frame: 0001; trigger tag: 49

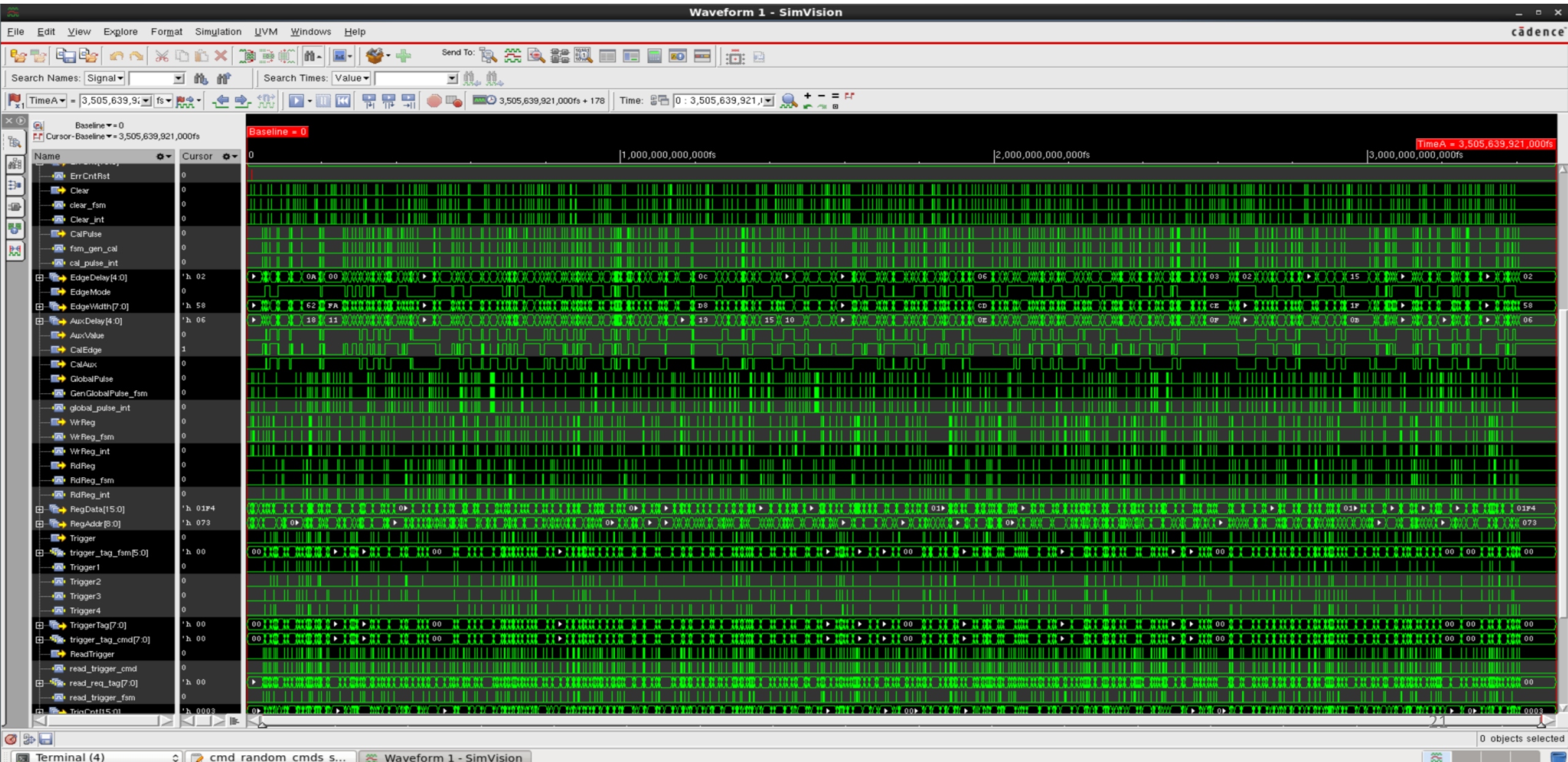
UVM_INFO
/home/cesar_gr/RD53B/work/sim/../../../../cds/./sim/verification_environment/cmd/sv/cmd_checker.sv(102)
@ 40047393000: uvm_test_top.m_env.m_cmd_analysis_env.m_cmd_checker [CMD_CHECKER_MATCH] CAL      Chip
#31,      calEdge mode: 1, calEdge delay: 3, calEdge width: 85, calAux mode: 1, calAux delay: 23
encoded cmd matches decoded cmd CAL      Chip #31,      calEdge mode: 1, calEdge delay: 3, calEdge width:
85, calAux mode: 1, calAux delay: 23

UVM_INFO
/home/cesar_gr/RD53B/work/sim/../../../../cds/./sim/verification_environment/cmd/sv/cmd_monitor.sv(282)
@ 42399649000: uvm_test_top.m_env.m_cmd_env.m_cmd_master_agent.m_cmd_monitor [COMMAND_MONITORING]
TRIGGER Positions of trigger during frame: 1011; trigger tag: 23

UVM_INFO
/home/cesar_gr/RD53B/work/sim/../../../../cds/./sim/verification_environment/cmd/sv/cmd_checker.sv(102)
@ 42449697000: uvm_test_top.m_env.m_cmd_analysis_env.m_cmd_checker [CMD_CHECKER_MATCH] WRITE
REGISTER      Chip #31,      no auto-increment, address VCAL_HIGH,      data c8 encoded cmd matches decoded
cmd WRITE REGISTER      Chip #31,      no auto-increment, address VCAL_HIGH,      data c8

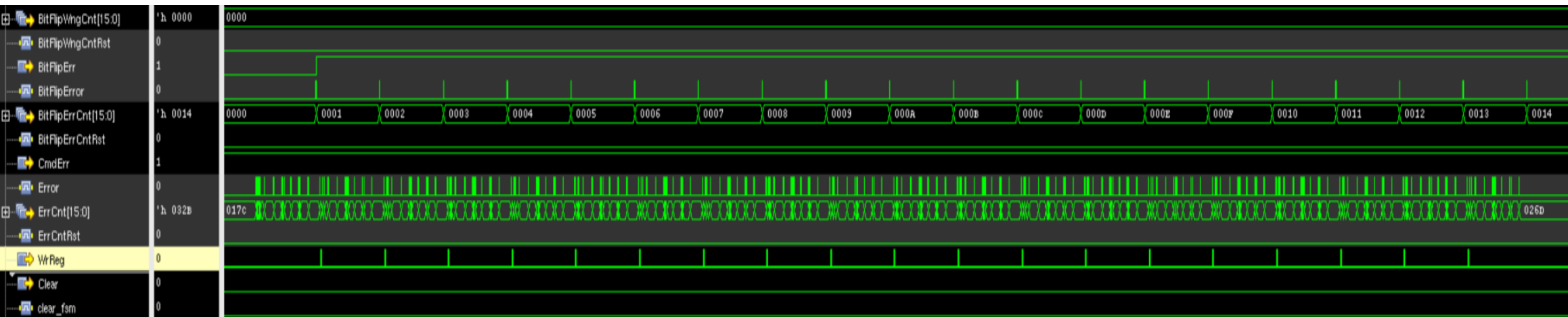
UVM_INFO
/home/cesar_gr/RD53B/work/sim/../../../../cds/./sim/verification_environment/cmd/sv/cmd_checker.sv(102)
@ 42599841000: uvm_test_top.m_env.m_cmd_analysis_env.m_cmd_checker [CMD_CHECKER_MATCH]
```

Over 2000 commands sent to the Command Decoder



Example of Verification Catching Bugs: Command Error Test

- I create a Command Error by sending a command with an invalid frame.
- When the following is sent instead of a Cmd Error raised, the command is sent:
 - [WrReg, ChipId][Data, Data][Data, Data][Data, **Invalid**]



Verification of Full RD53B Chip

- **What does it take to verify a full chip?**
 - A large number of tests written
 - REMEMBER: Over 119K lines of code written just for verification
- Large number of tests necessary to ensure complete **code coverage**.
- Overall 96% of code covered
 - Excluded Analog (vcd/ams) verification

Name	Block Covered Grade	Toggle Covered Grade	Code Covered
(no filter)	(no filter)	(no filter)	(no filter)
pixel_chip	95.99%	82.49%	70305326 / 82533720 (85...)
ChipBottom	83.14%	76.67%	648606 / 819186 (79.18%)
PixelArrayReadout	82.57%	75.59%	535997 / 681400 (78.66%)
TwoFFSyncNoCmdResetB	100%	33.33%	4 / 8 (50%)
RINGOSC_BLOCK_A	90.24%	73.73%	613 / 813 (75.4%)
RINGOSC_BLOCK_B	88.67%	100%	2752 / 2792 (98.57%)
DigitalChipBottom	95.15%	81.73%	106553 / 127824 (83.36%)
ResetPulseCalGenerator	99.15%	96.43%	279 / 286 (97.55%)
SelfTrigger	100%	12.1%	2513 / 3058 (82.18%)
ChannelSync	96.47%	75.67%	327 / 403 (81.14%)
CommandDecoder	98.07%	89.08%	1326 / 1425 (93.05%)
GlobalConfiguration	98.08%	83.44%	6758 / 7913 (85.4%)
TriggerTable	93.51%	88.1%	34904 / 39180 (89.09%)
DataConcentrator	96.05%	83.2%	36594 / 43761 (83.62%)
CdcResetSyncAurora	100%	100%	21 / 21 (100%)
CdcResetSyncDataMerger	100%	100%	21 / 21 (100%)
OutputCdcFifoAurora	100%	99.01%	1225 / 1237 (99.03%)
ServiceData	81.65%	87.59%	1260 / 1464 (86.07%)
ServiceCdcFifoAurora	100%	92.51%	1004 / 1084 (92.62%)
auroraDesData[0]	n/a	100%	2 / 2 (100%)
auroraDesData[1]	n/a	100%	2 / 2 (100%)
auroraDesData[2]	n/a	100%	2 / 2 (100%)
auroraDesData[3]	n/a	0%	0 / 2 (0%)
auroraDesData[4]	n/a	100%	2 / 2 (100%)
auroraDesData[5]	n/a	100%	2 / 2 (100%)
auroraDesMonitor[0]	n/a	100%	2 / 2 (100%)
auroraDesMonitor[1]	n/a	100%	2 / 2 (100%)
auroraDesMonitor[2]	n/a	100%	2 / 2 (100%)
auroraDesMonitor[3]	n/a	0%	0 / 2 (0%)
auroraDesMonitor[4]	n/a	100%	2 / 2 (100%)
auroraDesMonitor[5]	n/a	100%	2 / 2 (100%)
DeserAurora	95.33%	64.3%	13168 / 20074 (65.6%)
auroraMergedData	n/a	100%	2 / 2 (100%)
MergerDataArbitrer	100%	86.67%	54 / 58 (93.1%)
auroraMergedMonitor	n/a	100%	2 / 2 (100%)
MergerMonitorArbitrer	100%	86.67%	54 / 58 (93.1%)

Conclusion

- RD53 Collaboration is working on the production read-out chips for ATLAS and CMS
- ATLAS Chip Submission on Jan. 15, CMS a few months later
- Verification is a cornerstone of chip design and fabrication
- Making up 60-70% of the chip design, a comprehensive and flexible verification methodology is necessary
- Universal Verification Methodology and SystemVerilog used to ensure the proper behavior of the chip design
- Extensive simulation and verification program essential for the design of the final chip

Backup

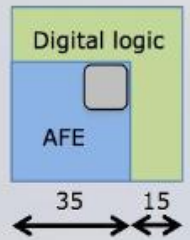
RD53B New Features

- Selected Diff. Front End for ATLAS, Lin. FE for CMS
- Added edge, top, and corner pixel biases
- Upgraded calibration injection & corrected column variation
- New hit synchronization and ToT with 6b-to-4b compression
- Redesign of the startup and generation of reference voltages
- Improvement of SLDO and addition of low power mode
- Addition of overcurrent and overvoltage protection
- Redesigned PLL for lower jitter and robust locking
- Added trigger tags and new readout format with compression
- Added 2-lever trigger for ATLAS and self-trigger
- Added suppression of low charge isolated hit backgrounds
- Added data aggregation between chips
- Changed reset scheme to synchronous and added CMD activity reset
- Extensive triplication and SEU hardening
- Added new resistive temperature sensors and E-fuses for SN
- Added precision ToT and ToA
- Enlarged wire bond pads

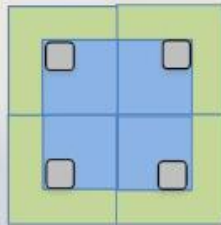
RD53A Pixel Floorplan

4

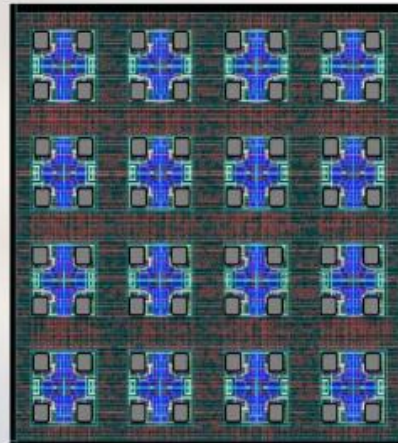
- Pixel matrix build from 8 x 8 pixel cores
- One Pixel Core contains multiple Pixel Regions with shared logic and trigger latency buffering
- FEs are placed as analog islands in the "digital sea" of synthesized core logic
- All cores are identical



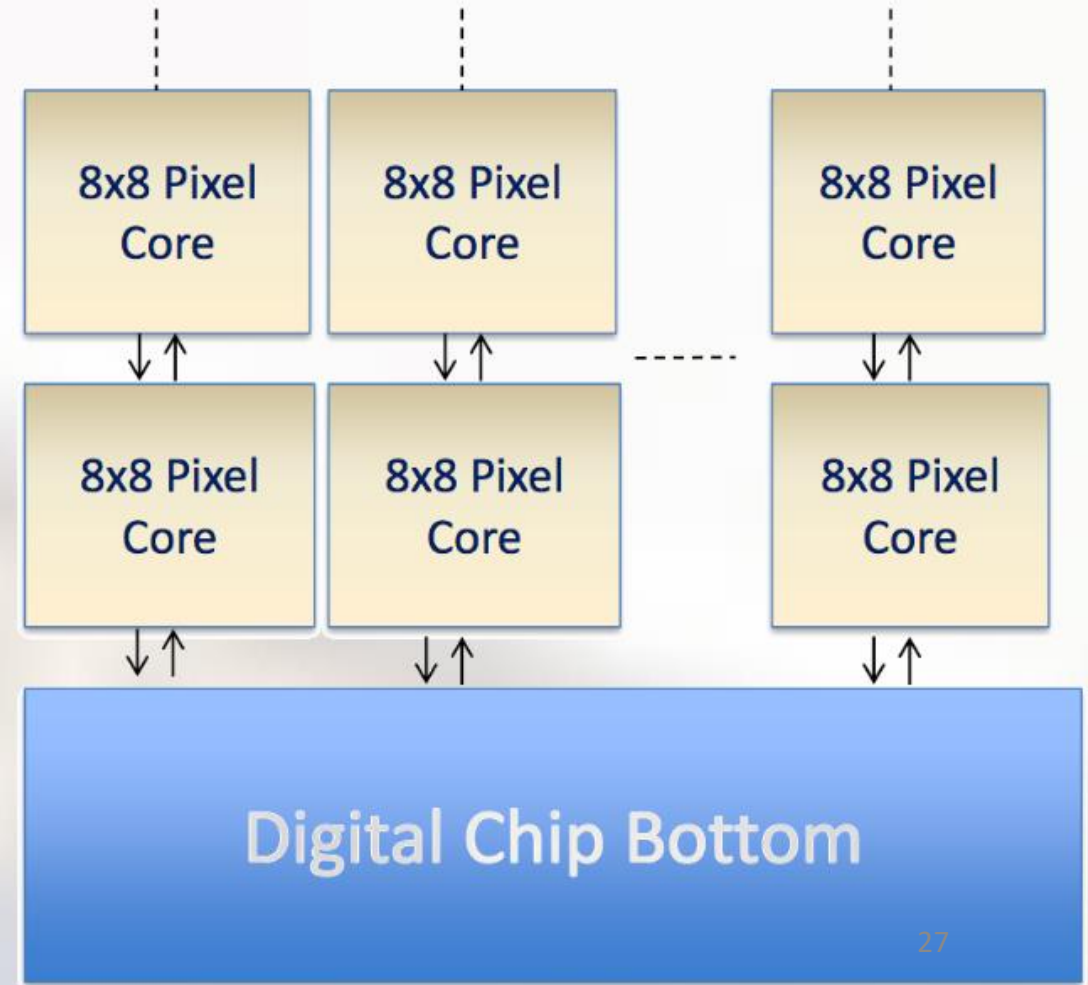
PIXEL



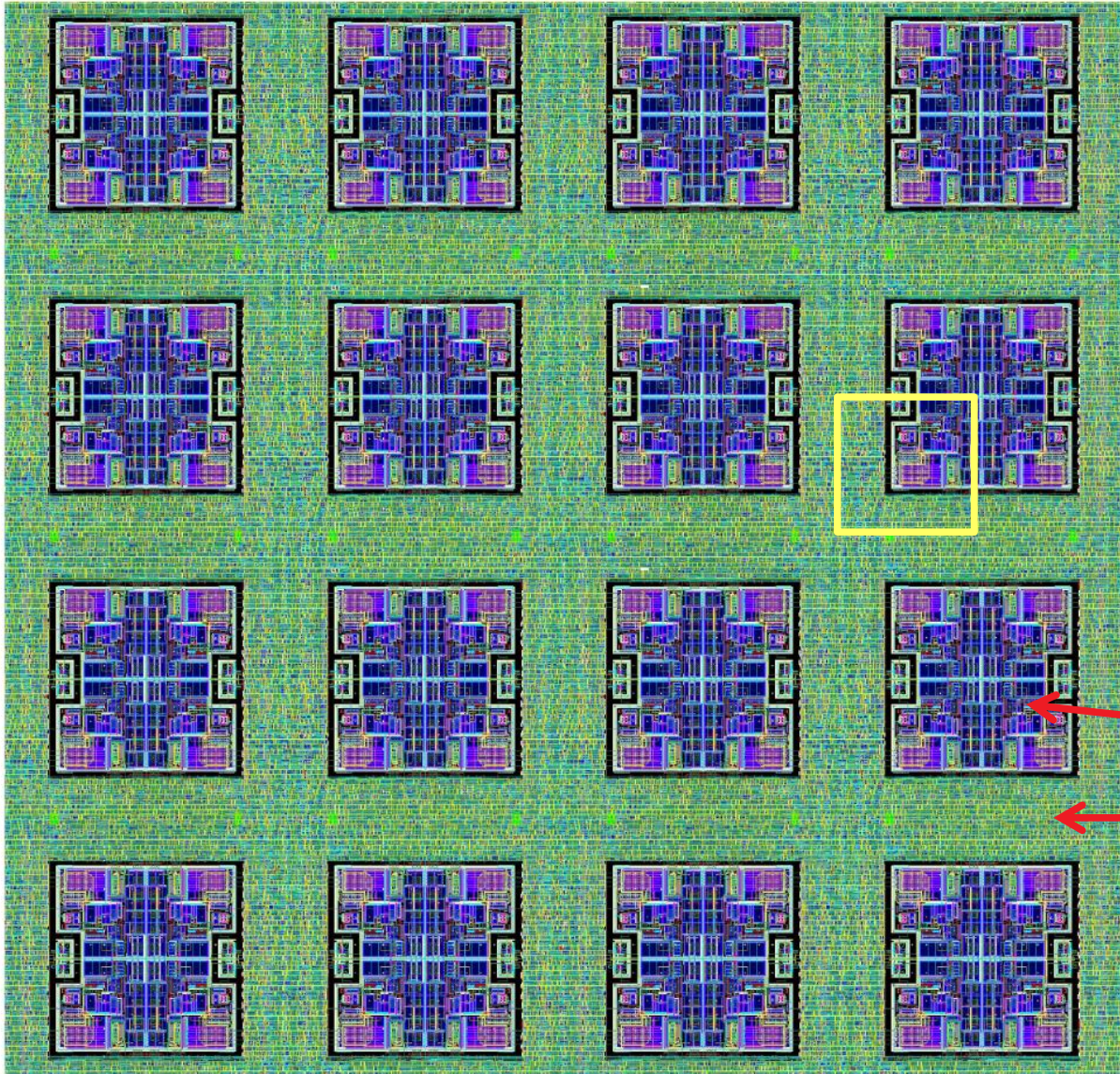
**ANALOG
ISLAND**



PIXEL CORE



One Core



One flat synthesized circuit

~ 200k transistors

64 pixels in 16 “analog islands”

Whole core is stepped
and repeated to make the
pixel matrix

Hand-drawn transistors

“compiled software”

RD53A: Powering

8A (4A), 12V

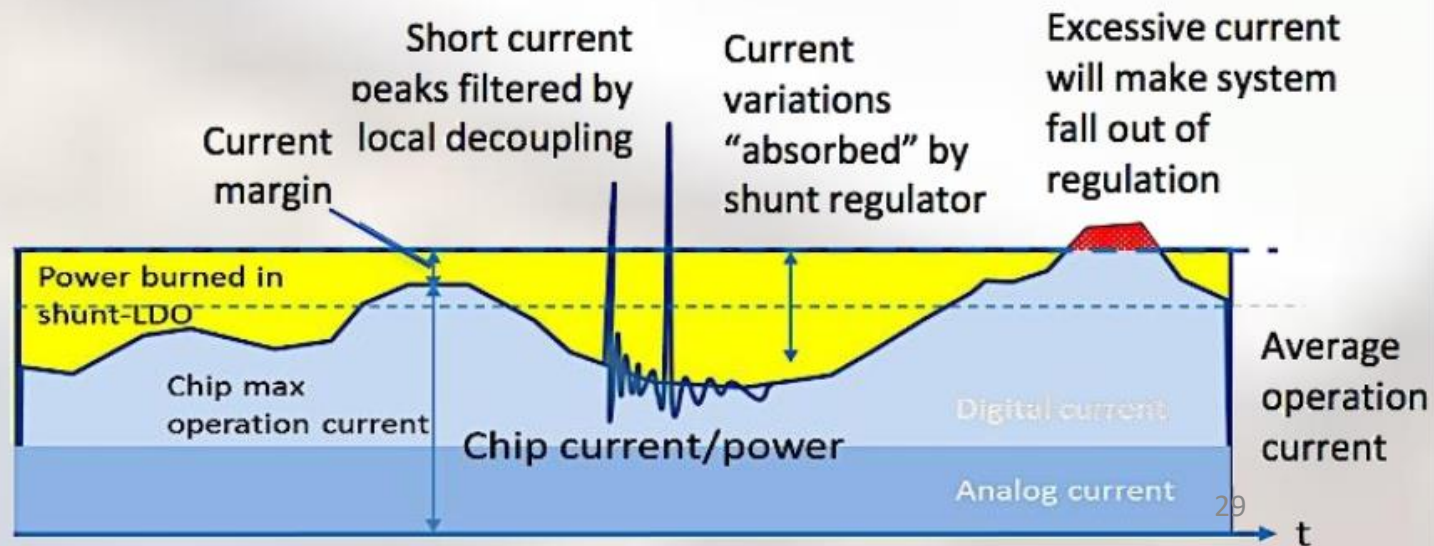
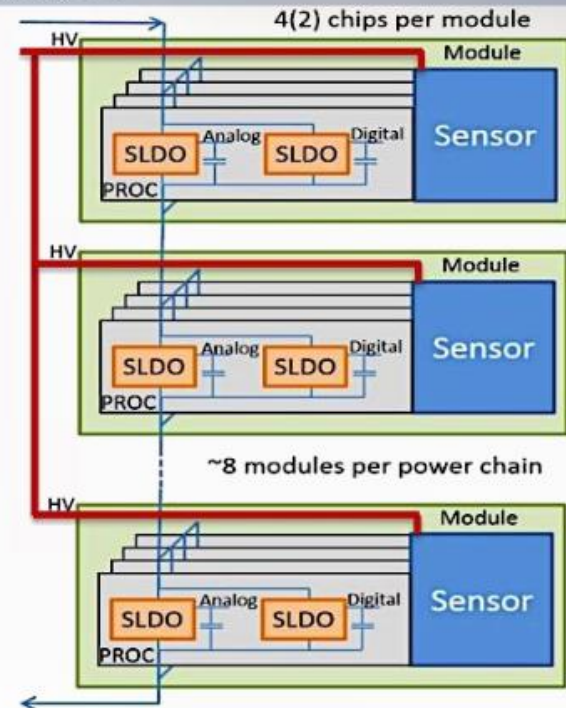
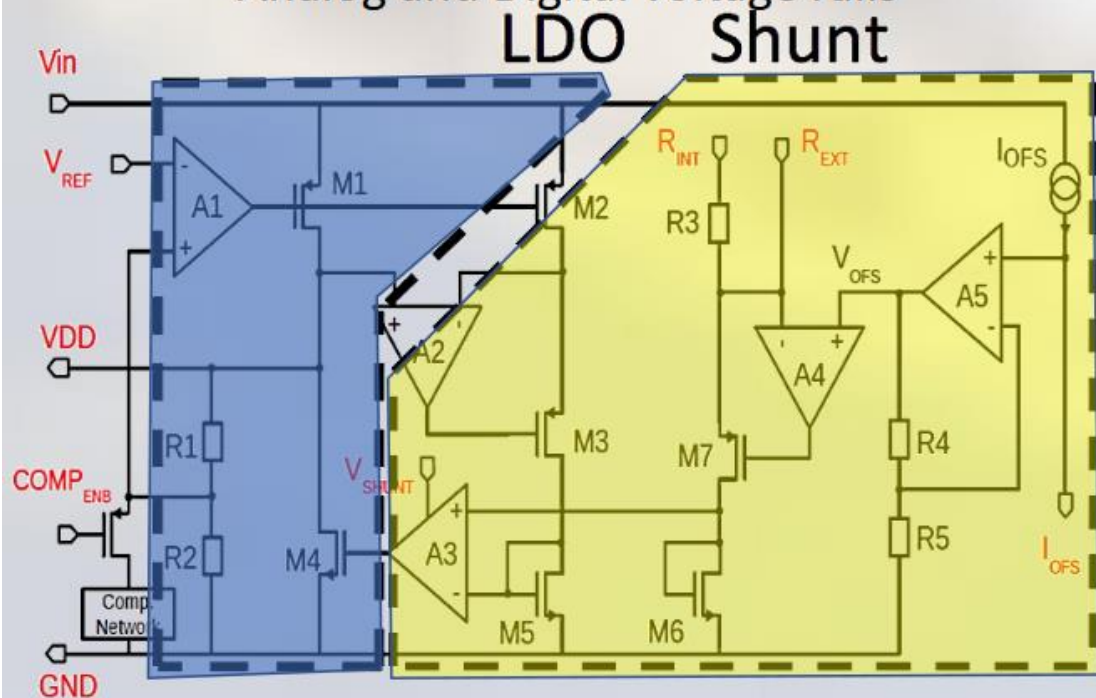
2

- **Baseline for powering the ATLAS and CMS HL-LHC pixel detectors: serial powering**

- Low mass, Not sensitive to voltage drop, Low noise
- Up to 4 chips in parallel resolve single chip failures

- **RD53A Shunt-LDO regulator**

- Low-drop linear voltage and a shunt regulator
- Three operational modes (direct, LDO and ShuntLDO)
- Analog and Digital voltage rails



Output from the Chip(s)

Chip Output Data:

- There are 1 to 4 Aurora64/66b @1.28GB/s encoded lanes that form a Simplex Aurora Channel. The Data has strict alignment. [always Same data type on all Lanes]
- Optionally it has one or two 320Mb/s (640Mb/s, if working) Aurora64/66b encoded Lanes that form a Simplex Aurora Channel only used for on chip data merging.

Aurora Channel contents:

Each Aurora Channel might contain **Pixel Data**, **Service Data** or **No Data**.

- **Pixel Data:** Continuous stream of 66 bit Aurora Frames, without separators. Each frame is identified by a '01' header followed by 64 bit of data.
- **Service Data:** Single Aurora Frame identified by a '10' header followed by 64 bit of data.
- **No Data:** Standard Aurora Idle Frame, also identified by a '10' header.

Service Data:

- A single Aurora Frames that contains the value of **two RD53 registers** (Global or Pixel).

Pixel Data:

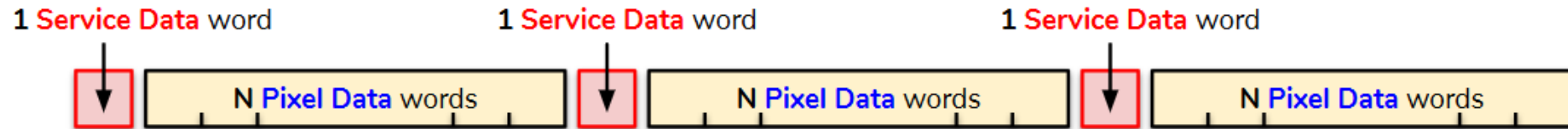
- All data coming from pixels is **split into 64 bit wide Aurora Frames**.
- Data is generated inside the chip and put in variable length streams.
- Each pixel chip always produces an unknown number of concatenated data streams.
- For each incoming Trigger an outgoing Event will be produced [no event suppression]

Output Data [1, 2, 3, 4 links]

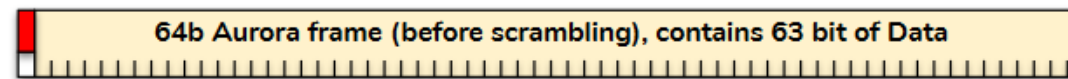
The Output Data Stream is sent on 1, 2, 3 or 4 different Aurora physical Lanes.
Each link is logically split in two separate channels:

Pixel Data and **Service Data** where the ratio between the two is user programmable.

1. Ratio **R** between Pixel Data and Service Data is user programmable.
2. As an example a ratio $R = (1 \text{ over } 50)$ allows for ~100Mb/s of Service Data



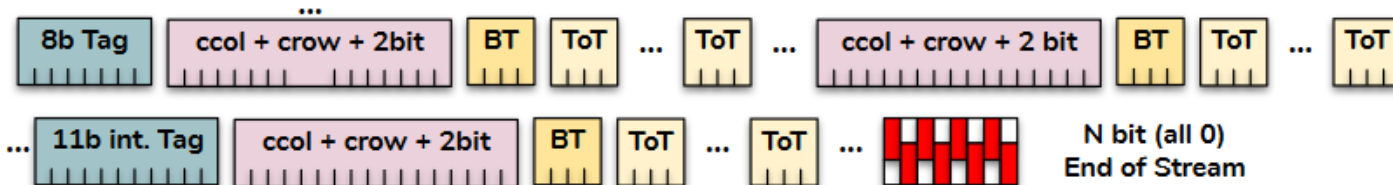
Pixel Data:



Header:



Possible Data:

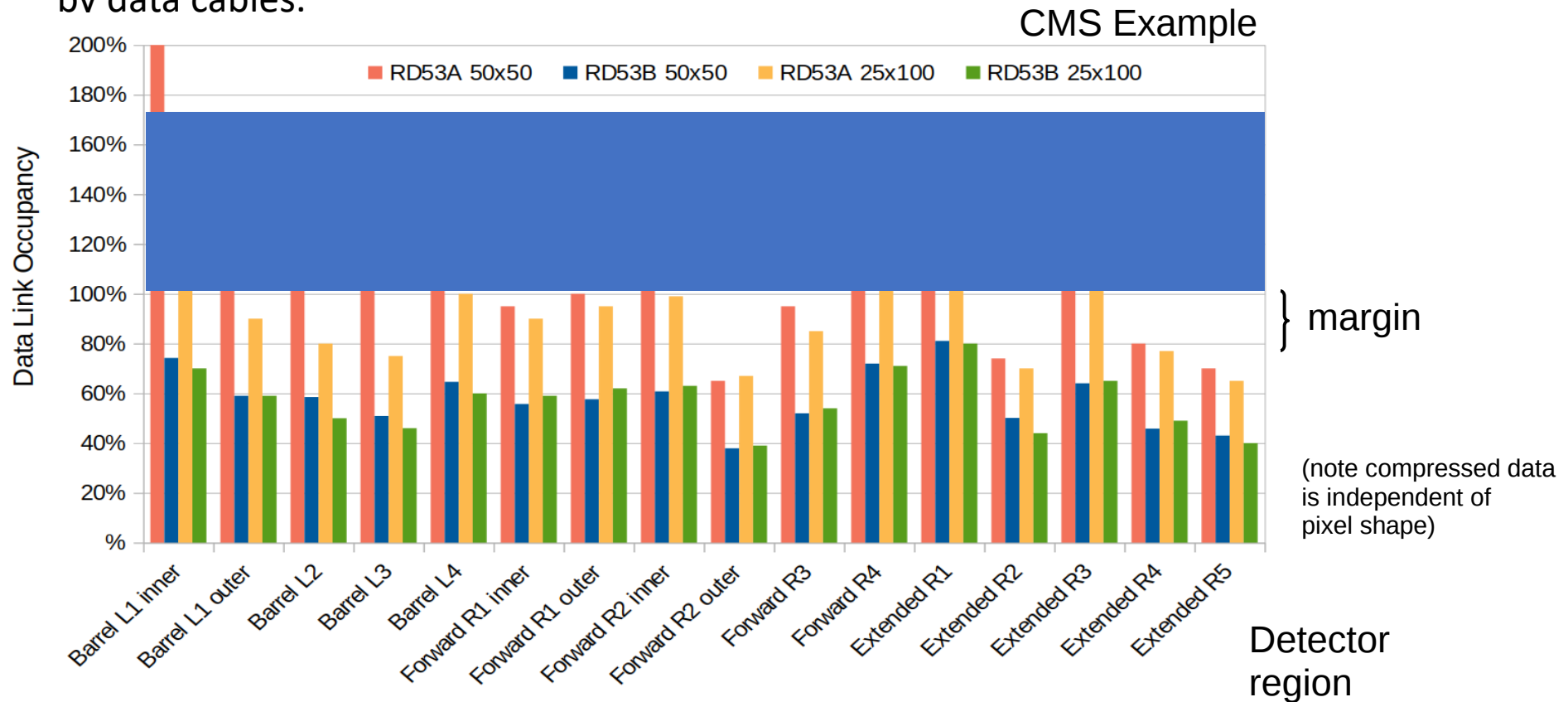


Service Data:



New Feature Highlight

- Encoding with lossless compression used to send data off chip.
 - Custom serial stream encoding to achieve compression AND be tolerant of corrupted fragments
- Important because, thanks to serial power, services volume (and mass) is dominated by data cables.



For designed serv

```
module CommandDecoder (
```

```
//
```

```
// Outputs
```

```
output logic      Trigger,
```

```
output logic [7:0] TriggerTag,
```

```
output logic      ReadTrigger,
```

```
output logic [7:0] ReadTriggerTag,
```

```
output logic      Clear,
```

```
output logic      RdReg,
```

```
output logic      WrReg,
```

```
output logic      WrRegMode,
```

```
//
```

```
output logic [8:0] RegAddr,
```

```
output logic [15:0] RegData,
```

```
output logic [15:0] BCIDCnt,
```

```
output logic [15:0] TrigCnt,
```

```
output logic [15:0] ReadTrigCnt,
```

```
output logic [15:0] ErrCnt,
```

```
output logic      CmdErr,
```

```
output logic [15:0] BitFlipWngCnt,
```

```
output logic      BitFlipWng,
```

```
output logic [15:0] BitFlipErrCnt,
```

```
output logic      BitFlipErr,
```

```
output logic [15:0] SkippedTriggerCnt,
```

```
output logic      SkippedTriggerCntWng,
```

```
//
```

```
// GlobalPulse
```

```
output logic      GlobalPulse,
```

```
// Trigger signal. Uses TriggerTag.
```

```
// The 8 bit tag associated to each Trigger signal
```

```
// Signal used to readout data from the chip.
```

```
// The 8 bit tag associated data to ReadTrigger
```

```
// Clear the whole data path
```

```
// [Only if ChipId matches]
```

```
// [Only if ChipId matches]
```

```
// 0 if Single WrReg command, 1 if continuous mode
```

```
// Address of the register
```

```
// Data to be written in the addressed register
```

```
// synopsys keep_signal_name "BCIDCnt" // BCID counter value
```

```
// synopsys keep_signal_name "TrigCnt" // Trigger counter value
```

```
// synopsys keep_signal_name "ReadTrigCnt" // ReadTrigger counter value
```

```
// synopsys keep_signal_name "ErrCnt" // Error counter value
```

```
// There is an Error
```

```
// synopsys keep_signal_name "BitFlipWngCnt" // BitFlip Warning counter value
```

```
// There is a BitFlip warning
```

```
// synopsys keep_signal_name "BitFlipErrCnt" // BitFlip Error counter value
```

```
// There is a BitFlip error
```

```
// synopsys keep_signal_name "SkippedTriggerCnt" // Skipped Trigger counter value
```

```
// There have been skipped triggers . . . . . [to ServiceData]
```

```
// Signal used to generate all GlobalConfiguration pulses
```

devel RD53B / rtl / top / + v



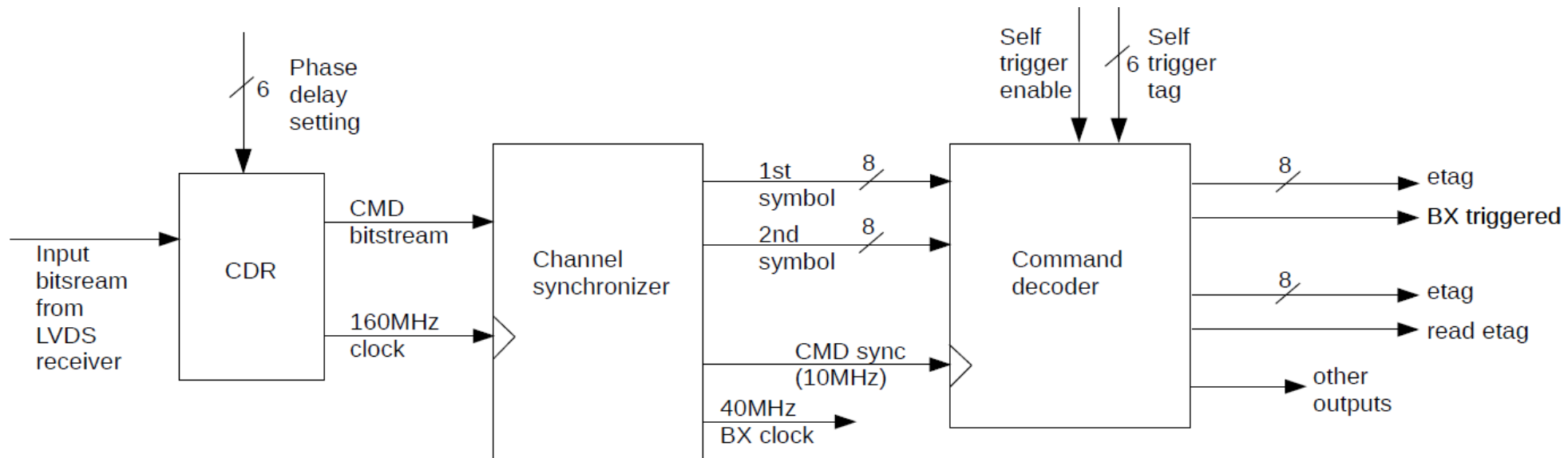
Checked how the Clear command is processed inside the chip. Now everyth

Roberto Beccherle authored 5 days ago

Name	Last commit	Last update
..		
ChipBottom.sv	Checked how the Clear command is processed inside the chi...	5 days ago
CoreColumn.sv	Use VCAL* according to V* naming convention	8 months ago
PixelArray.sv	BUG: fixed hit-or endianness mismatches across the design hie...	4 weeks ago
RD53B.sv	FIX: Now if the ChipId changes while a Slow command is exec...	6 days ago

Channel Synchronizer

- In order to lock to a frame alignment we use a Channel Synchronizer
- It receives a “sync” command from the input bitstream
- C.S. then lines up with the start of the frame (align itself to frame boundaries).
- Sync command sent multiple times to ensure locking of frame alignment.
- Once locked, C.S. starts command transmission to the Command Decoder



Verification approach

1. Constrained-random tests

- Random inputs (e.g. hits and triggers at operating conditions, from physics Monte Carlo simulations, input commands with random errors...)
- Automated pixel array verification
- Semi-automated command, configuration and aurora verification
→ increase automation: e.g. configuration reference model, self-correction of errors as in the protocol

2. Directed tests

- Specific test cases aimed to verify single functions and specific test cases not covered 1.
 - mostly used for custom command sequences, injections, etc.
- Quite a few tests checked by looking at waveforms for RD53A. Aim to automate (assertions, ref.model, etc.

3. Analog/digital interface

- Generation of **stimuli for full-spice analog simulations** (dump *vcd* for analog designers)
- Others: mixed signal simulations in analog and/or dedicated tests in digital (AMS model + Real Number Model planned for analog blocks of Analog Chip Bottom, AFEs RNM considered)

Interfacing UVM to the DUT

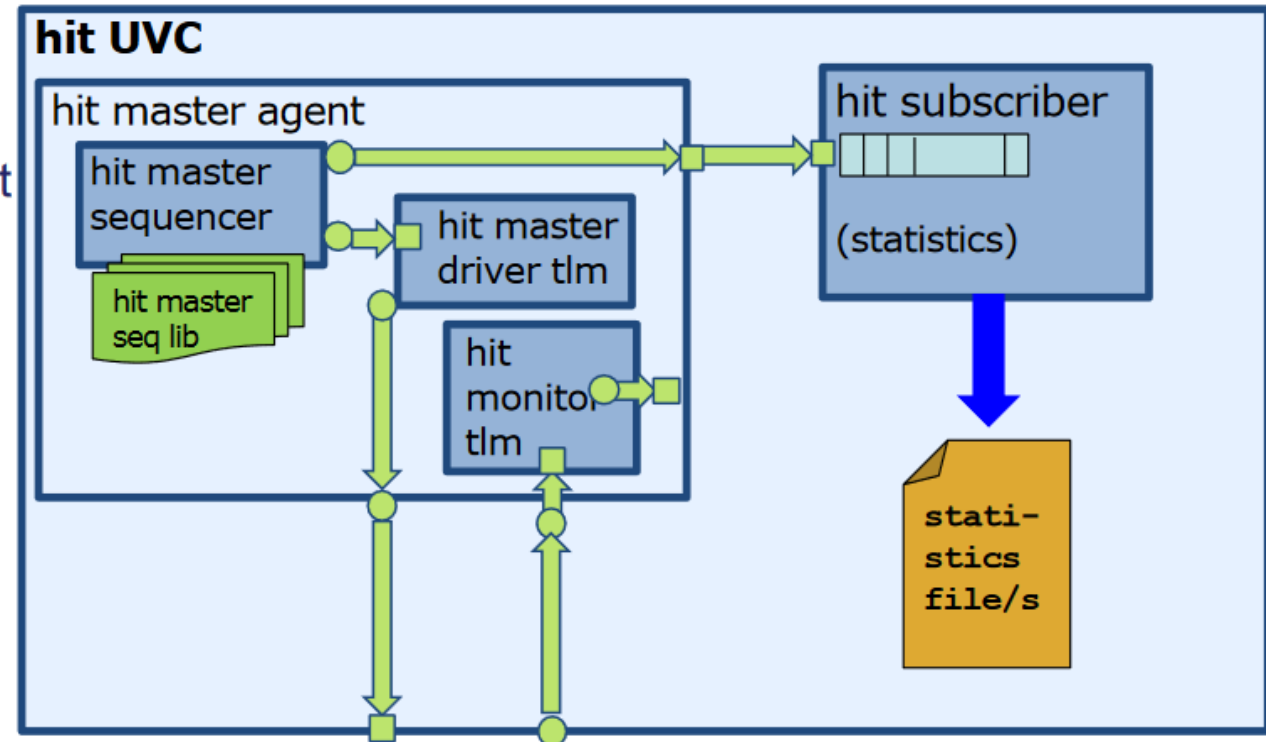
- SystemVerilog interfaces between UVM components and DUT
 - defined in the top level verilog module (we call it *pixel_chip_harness*)
 - linked to the UVM world by **setting** them in the ***uvm_config_db*** (in *pixel_chip_tb.sv*)
- Main interfaces and transactions defined:

Hit interface	Trigger interface	Cmd interface	Output data interface aurora	Analysis interface (optional)
• Analog input hit signal	• Input trigger signal	• Input commands	• Output of the Aurora receiver	• Virtual flag signals related to DUT status for statistical information collection (dead time, buffer occupancy, ...)

hit_trans	trigger_trans	cmd_trans	hit_trans	analysis_trans
<pre>+time_ref: int +hits: hit []</pre>	<pre>+time_ref: int</pre>	<pre>+cmd_type: cmd_type_t ... +chip_ID: [3:0] bit +reg_addr: GCR_addr_t ...</pre>	<pre>+time_ref: int +hits: hit []</pre>	<pre>... DUT-specific data members (e.g. pixel dead-time, buffer full) ...</pre>
hit struct: <pre>+charge: unsigned int +delay: unsigned int +col: unsigned int +row: unsigned int</pre>		Transaction with many fields to cover all command types (including configuration commands)	The aurora monitor builds a hit trans for the pixel array scoreboard	

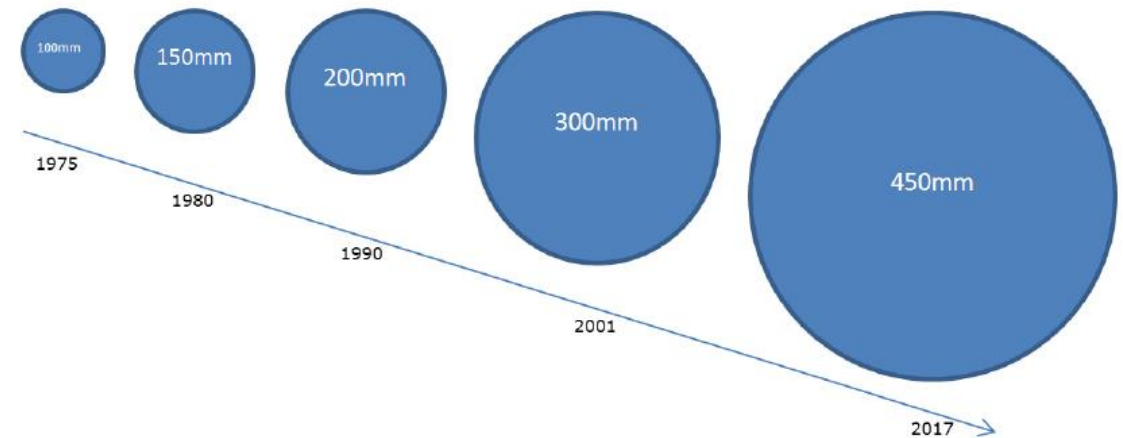
Example interface UVC: hit

- **Hit generation of input stimulus** handled by:
 - hit master **sequencer** (structural component that runs a sequence)
 - **sequence** (of transactions)
 - **driver** drives to the hit interface
- **Hit monitoring**
 - handled by the hit **monitor** in the agent (the latter is just a wrapper)
- The basic **objects** being exchanged are hit **transactions**
- **Statistic collection:**
 - Hit **subscriber** responsible of dumping/analyzing generated hits (histograms, hit rate computation,..)
- **Configurability through the tests and configuration database**
- *Note:* blocks `_tlm` created for DUT @TLM description: for RTL, additional driver/monitor with `_sig2tlm`, `_tlm2sig` (conversion from/to *signal* level)



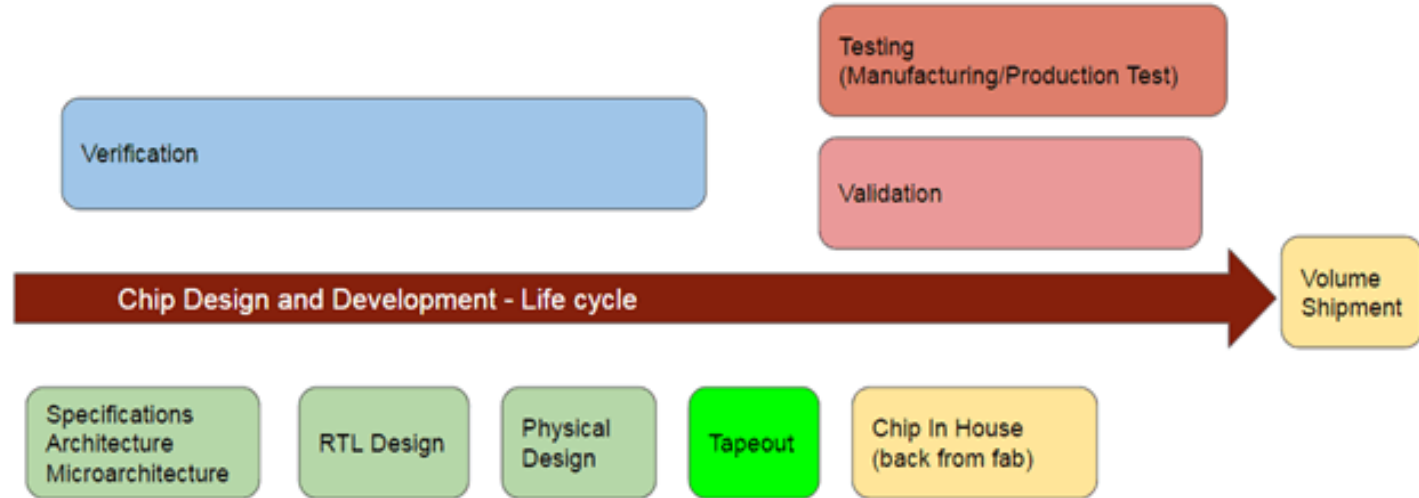
Why Verification is so Important?

- Increasing complexity of IC design means much higher chance of errors and bugs present in final product.
- Verification ensures (to an extent) the design is bug free and behaves as expected.
- This results in an overall faster design process which avoids major errors that could mean product recalls, time syncs, etc.



What is Verification?

- Ensure the design of the chip is accurate to specification/function/application.
- Basic Steps of Verifying the Design Under Test (DUT):
 - Generate stimulus
 - Apply stimulus to the DUT
 - Capture the response
 - Check correctness of response
 - Measure progress against overall verification goals
 - Ensure maximal coverage



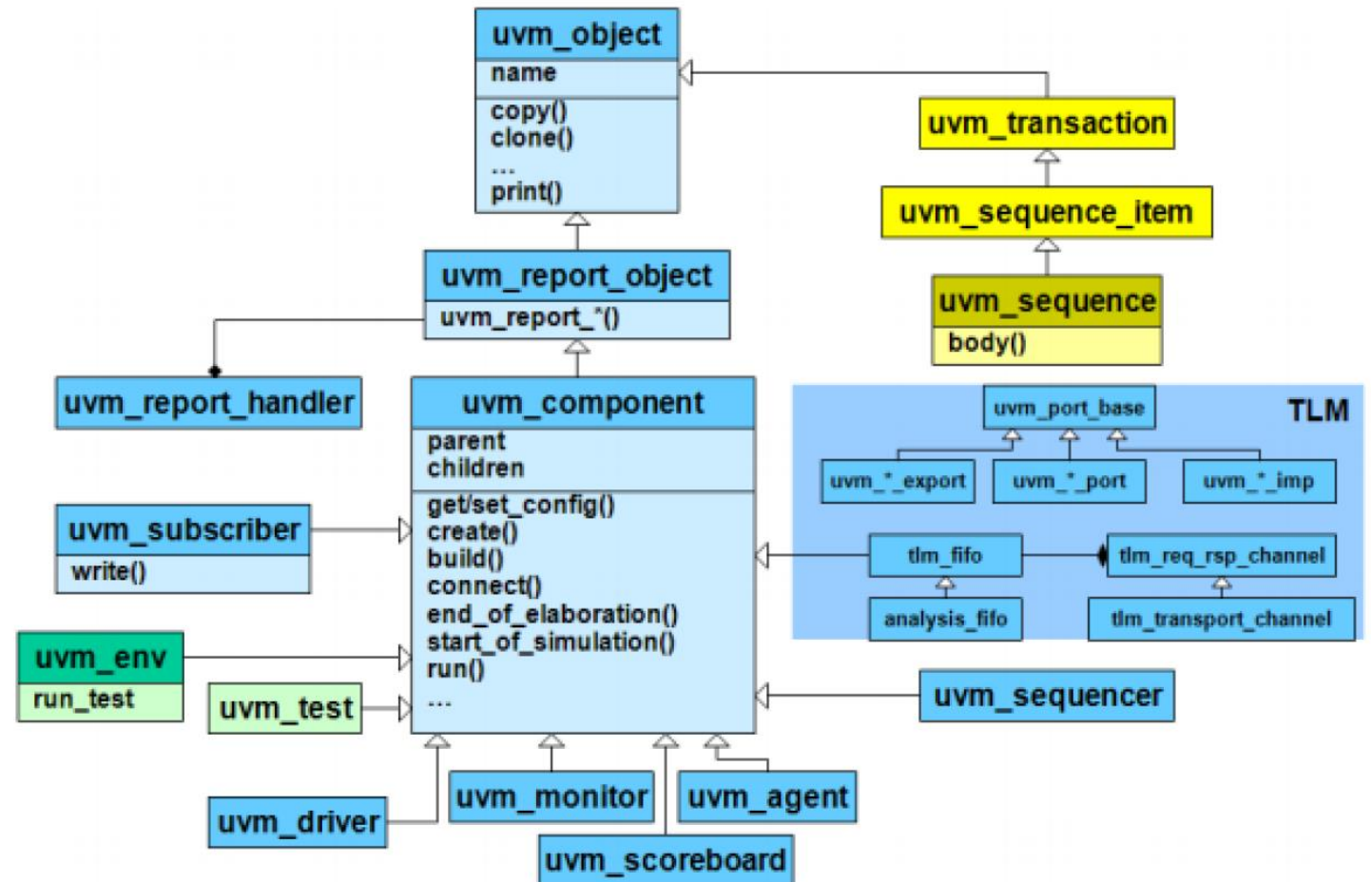
[2]

Universal Verification Methodology (UVM)

- Created in 2011 by Accellera to be used by all three major electronic design automation (EDA) companies: Cadence, Mentor, Synopsis
- Pre-built library and extensive documentation as guidance to reach greatest coverage in verification in a highly efficient manner.
- Contains many useful features:
 - Standard sets of base classes for data and environment
 - Utilities for managing log files and inter-process communication
 - Highly customizable reporting features.
 - Design for reusability

Top-down design of UVM Library

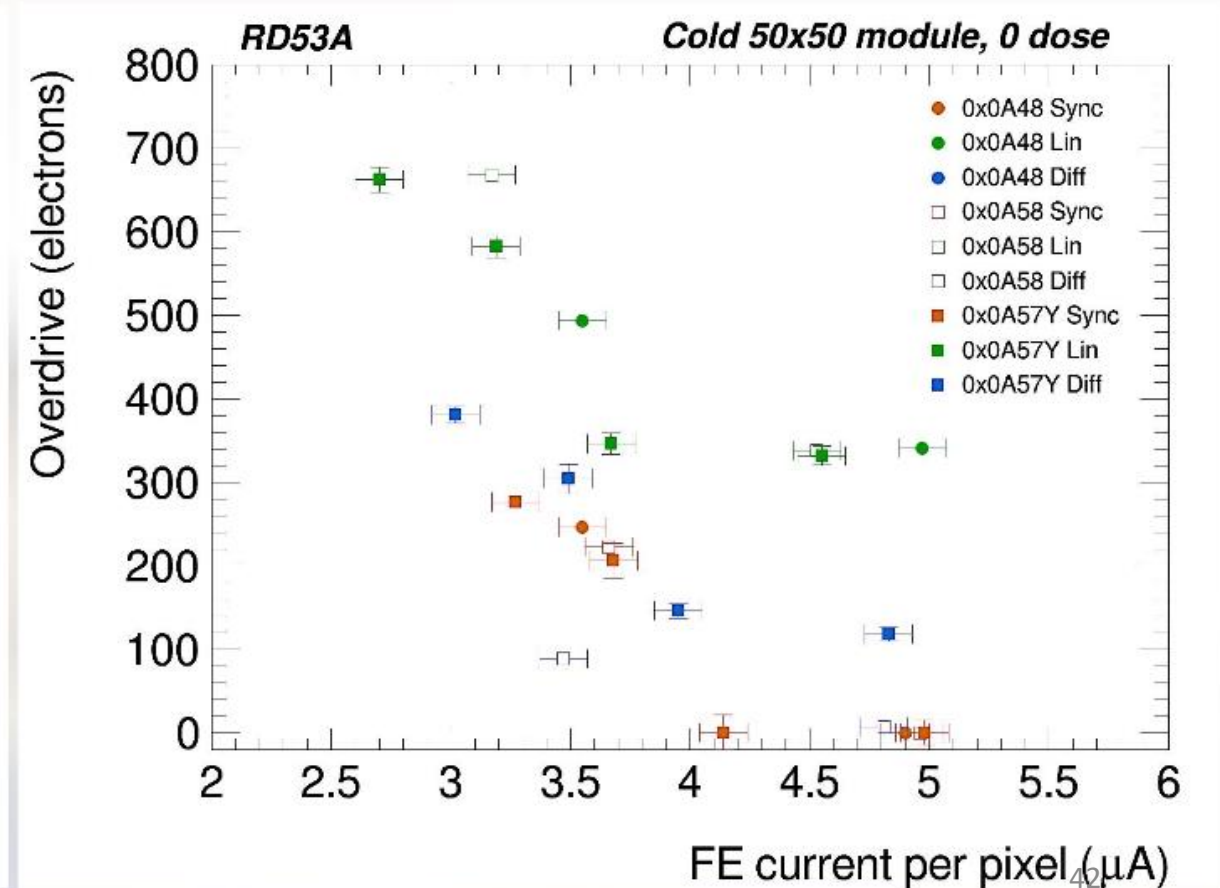
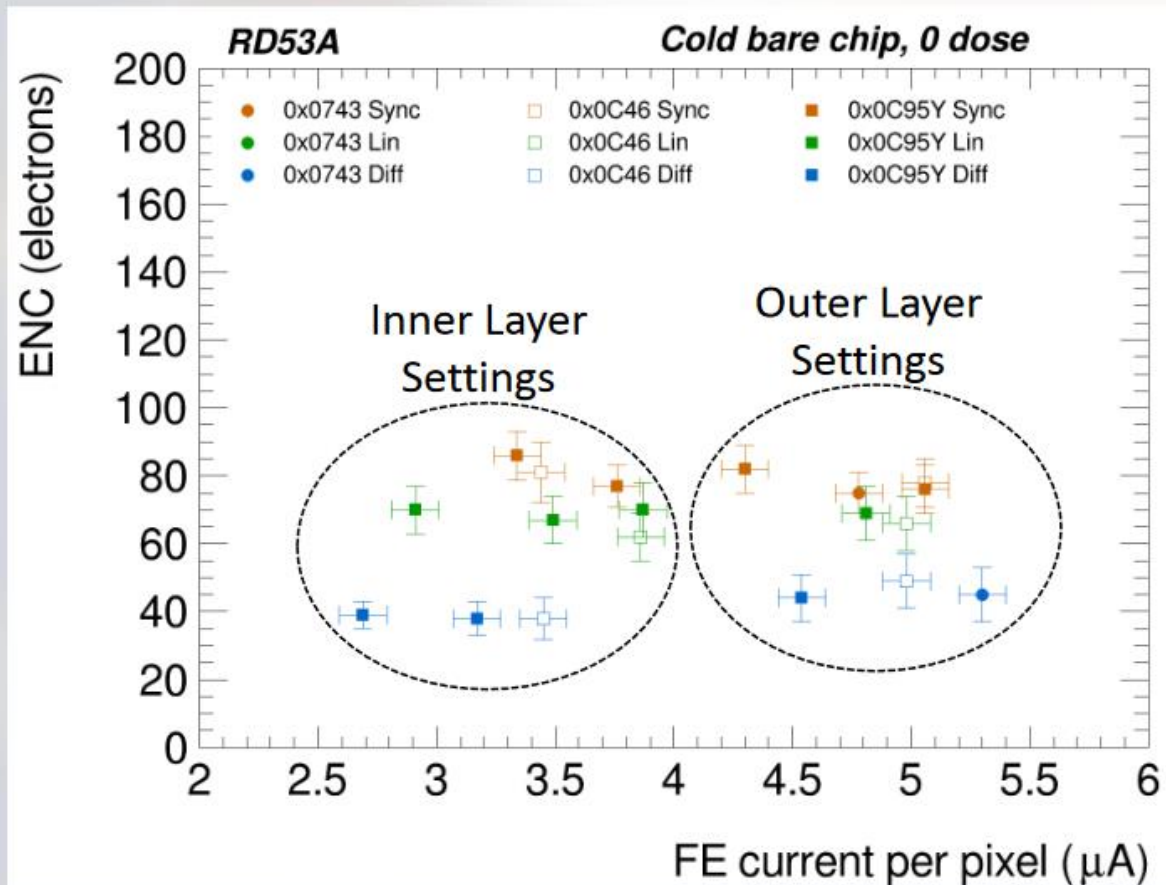
- Classes inherited from **uvm_object**
- **uvm_component**: Used for structural classes
 - Part of the framework for the full simulation run time.
 - Ex: uvm_driver, uvm_monitor, etc.
- **uvm_transaction**: data item or sequence item
 - Multiple instances created and deleted during runtime.



RD53A Results: Analog FE Characterization

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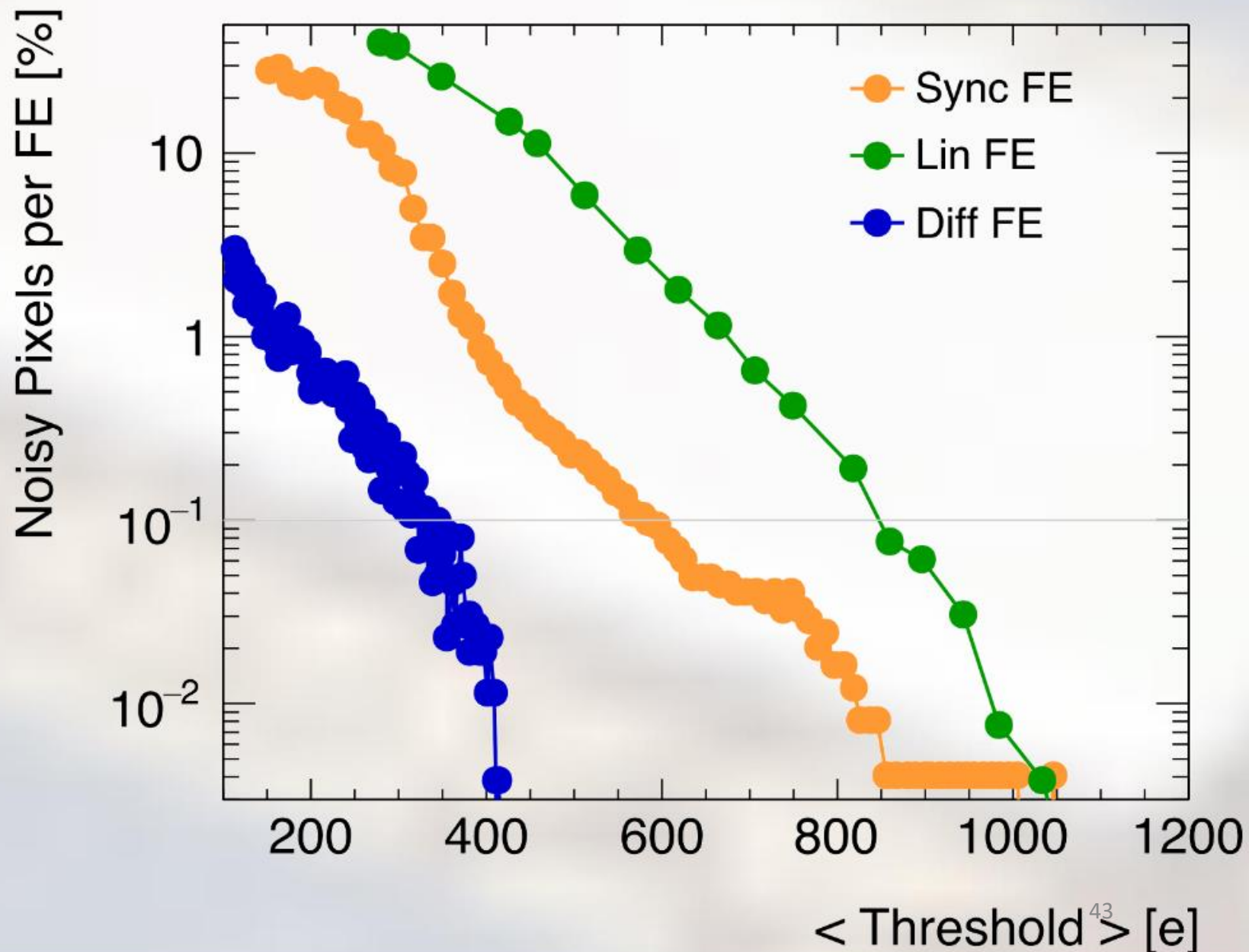
- Verify the functionalities of the three FEs
- Tests with bare chips and 50x50 μm^2 sensors with different settings
- Overdrive: difference between threshold and in-time threshold



RD53A Results: Analog FE Characterization

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- Measure how many pixels have noise occupancy $> 10^{-6}$ hits/bc as a function of the mean threshold
- Procedure:
 - ✓ tune
 - ✓ lower global threshold
 - ✓ retune pixel threshold (except for the SFE)
 - ✓ measure (in-time) threshold
 - ✓ measure noise
- Dependent on the tuning procedure (assumed that the threshold distributions is Gaussian)
- Cold Bare Chip

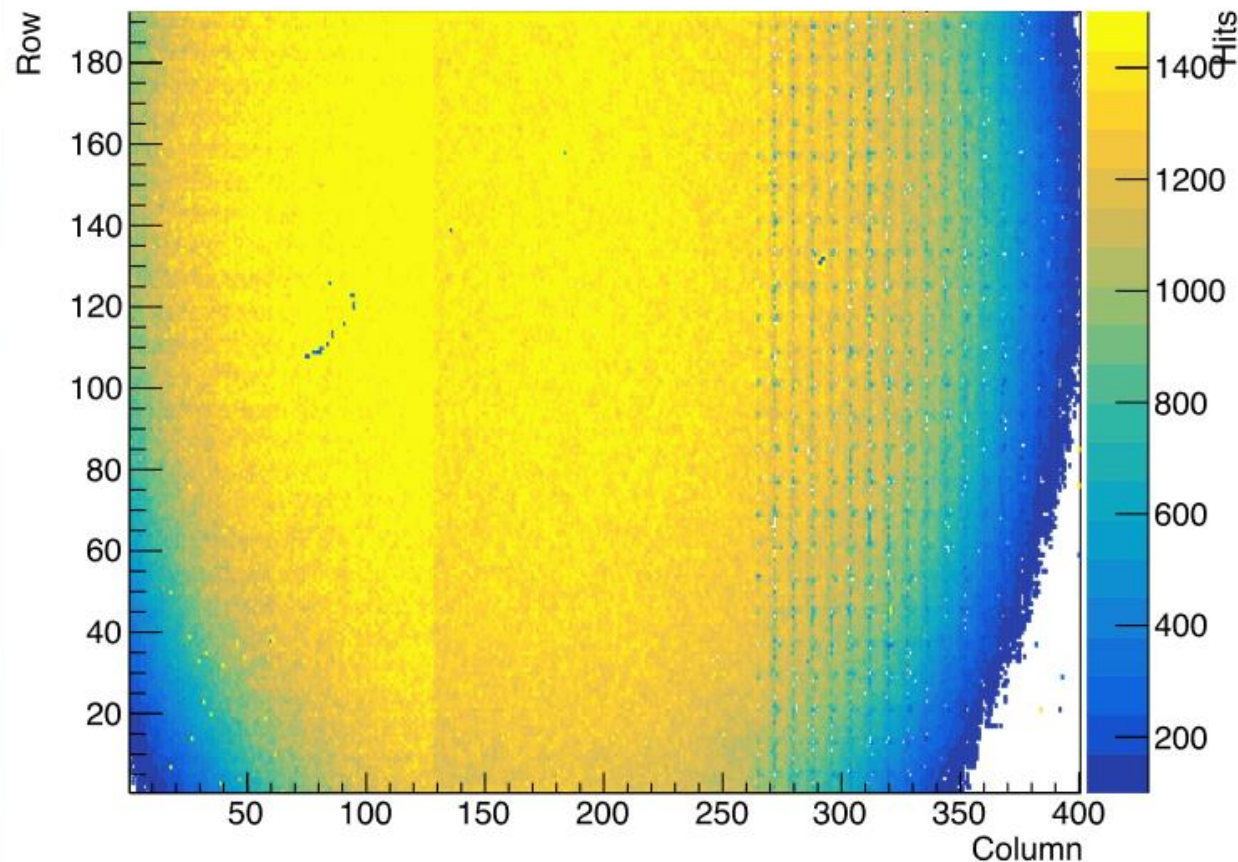


RD53A Results: Realistic Hit Rate

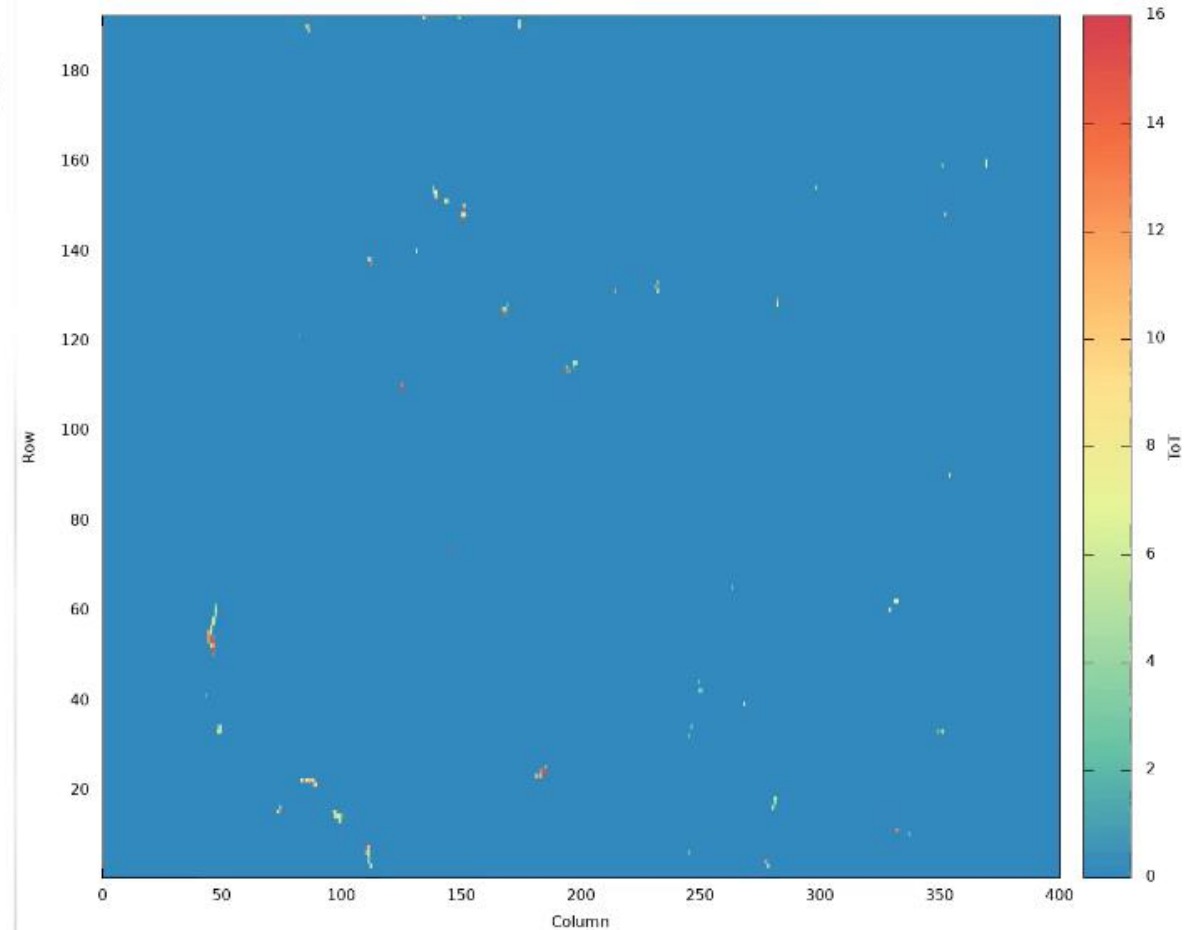
11

- Kr-85 beta source with activity 60 mCi (opening window 19 mm)
- Estimated hit rate: 7×10^{-4} hits/bc

OccupancyMap



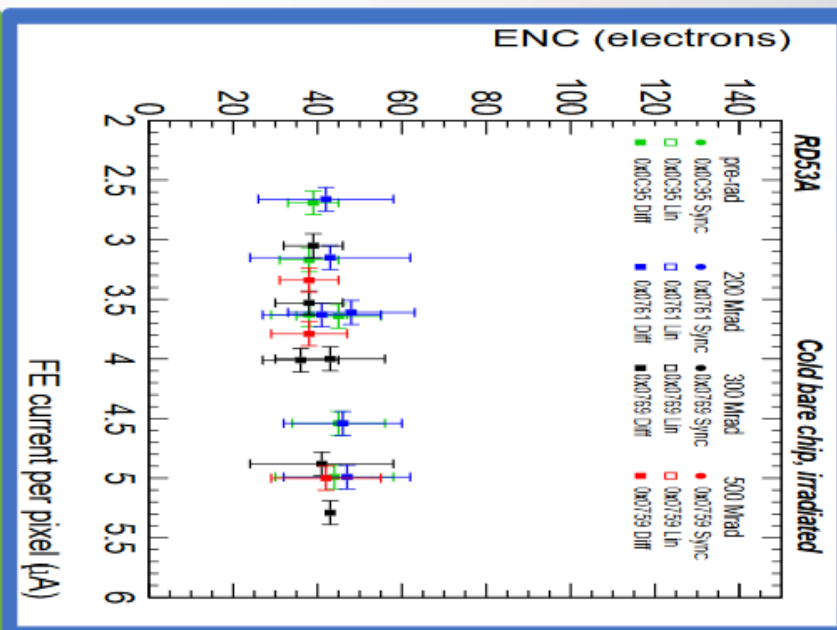
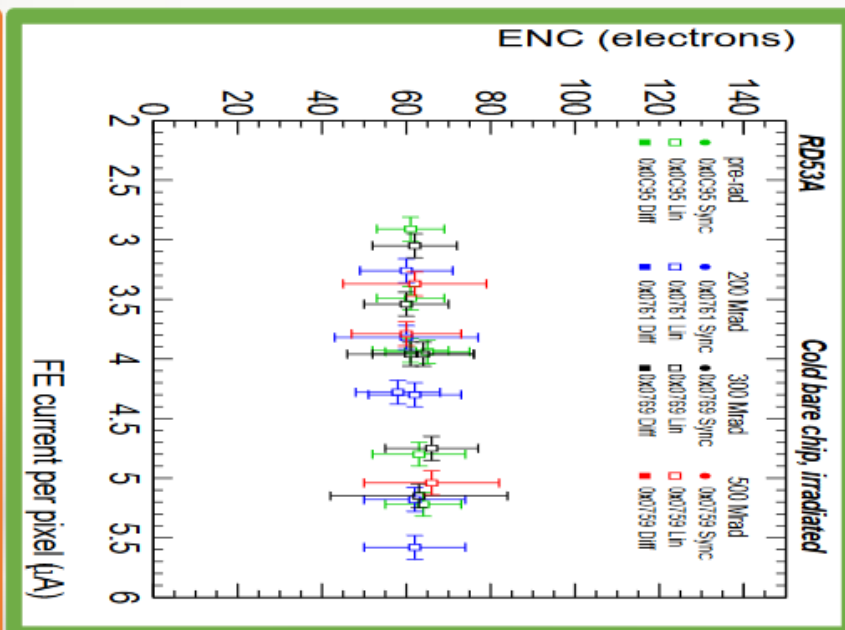
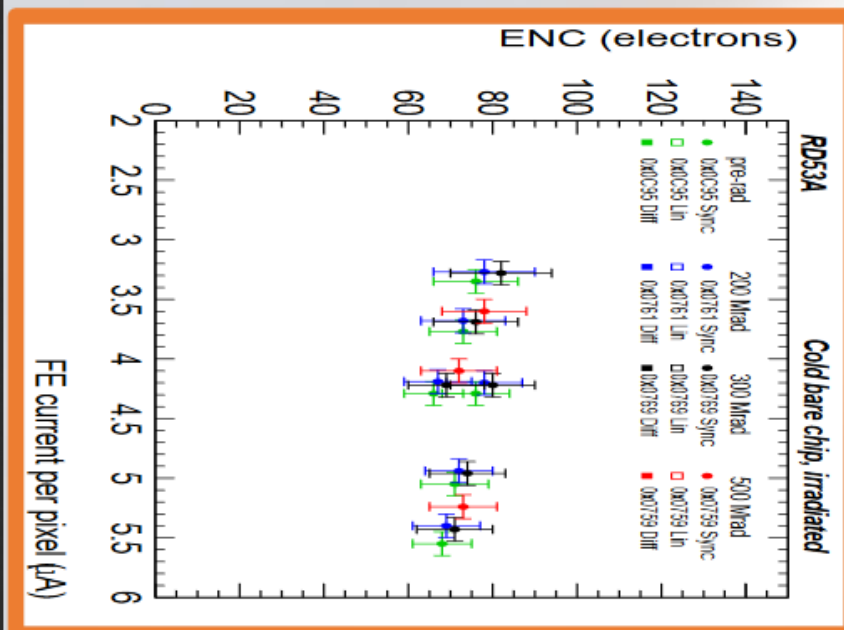
1-eventScreen



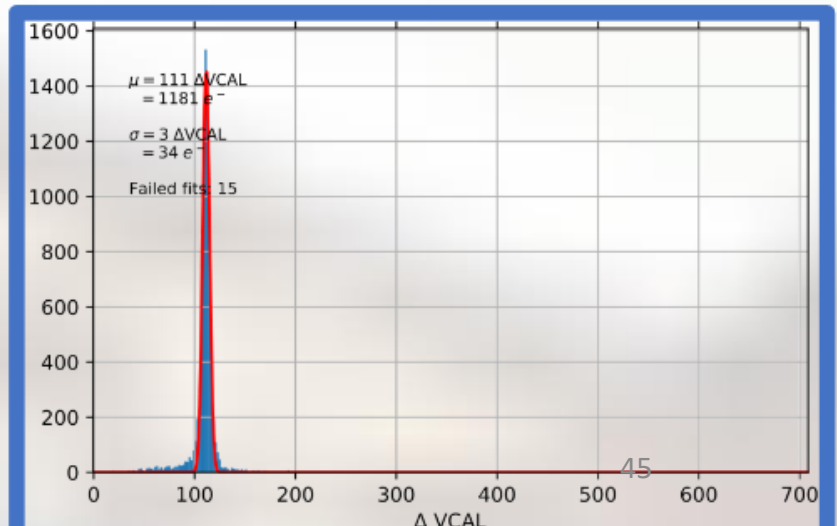
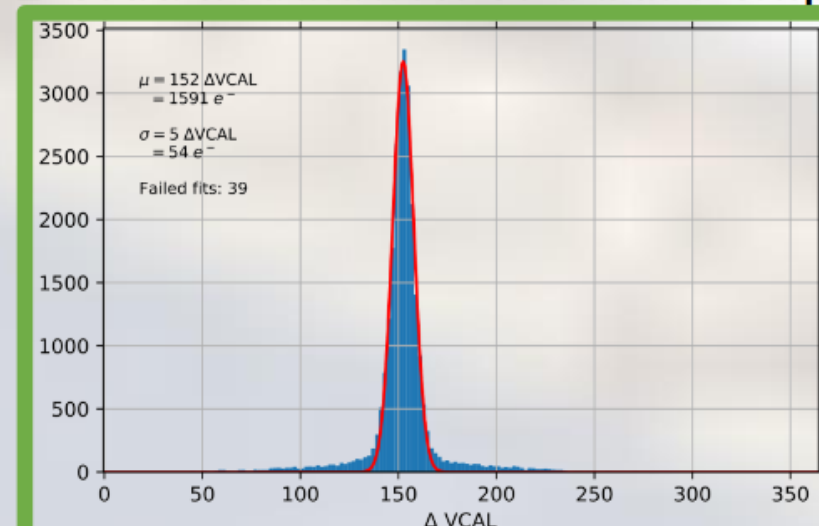
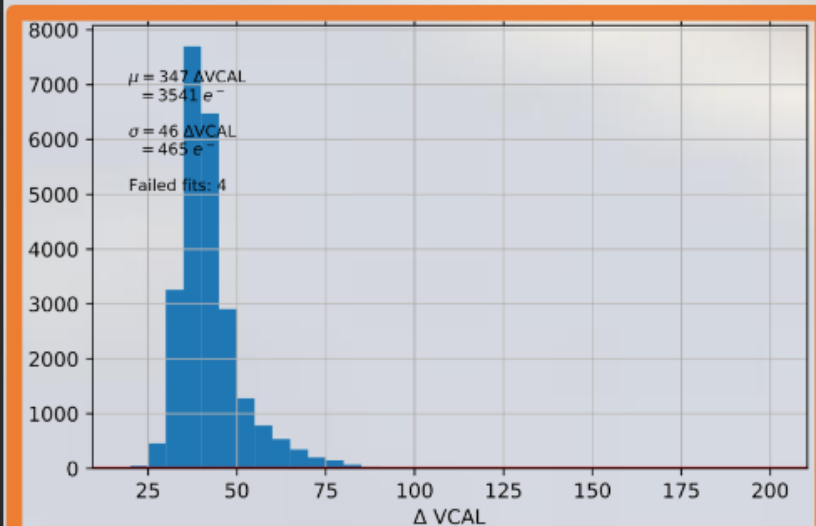
RD53A Results: Analog FE Characterization After Irradiation

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- Noise for different current settings (for 0, 200, 300, 500 Mrad)



- Threshold distribution after 1 Grad irradiation of a bare chip



References

1. Performance of the CMS Tracker Optical Links and Future Upgrade Using Bandwidth Efficient Digital Modulation - Scientific Figure on ResearchGate. Available from:
https://www.researchgate.net/figure/Cross-sectional-view-of-the-CMS-detector-11-The-HCAL-contains-and-measures-the_fig3_41217449
[accessed 3 Dec, 2019]
2. <https://anysilicon.com/verification-validation-testing-asicsoc-designs-differences/>
3. *Francesconi, Juan Ignacio et al. "UVM based testbench architecture for unit verification." 2014 Argentine Conference on Micro-Nanoelectronics, Technology and Applications (EAMTA) (2014): 89-94.*